MSP430™ Ultra-Low-Power Microcontrollers





ti.com/msp430 1H14

MSP430TM microcontrollers (MCUs) from Texas Instruments (TI) are 16-bit, RISC-based, mixed-signal processors designed for ultra-low power. Our MCUs offer the lowest power consumption and the perfect mix of integrated peripherals for thousands of applications – including yours. We also provide all of the hardware and software tools you need to get started today! Not only that, TI has a plethora of complementary components to meet your needs. Learn more today at ti.com/msp430.

Ultra-low power

Battery Life > 20 Years

- <100 μA/MHz
- 0.1µA RAM Retention
- <1µA RTC Mode

More Performance Without Sacrificing Battery Life

- 7 Low-Power Modes
- Instant Wakeup
- Autonomous Peripherals



Integration

Advanced Peripherals

- High-Performance Analog
- Optimized Serial Communications
- Operate in Low-Power Modes

Minimize Physical Footprint and Bill of Materials

- USB
- LCD Drivers
- Sigma Delta ADCs



Ease of Use

Development

- Start with MSP430 LaunchPad **Evaluation Kit**
- Comprehensive Software Portfolio
- Application-Specific Ecosystem

Support

- Code Examples
- Direct Support Available at ti.com/e2e-msp430
- Developer Community at 43oh.com



Grow with MSP

Scale Your Applications

- 400+ Devices
- Up to 512 KB Flash and 64 KB RAM
- 25+ Package Options

Unlimited Possibilities with TI

- Data Collection
- Wireless Connectivity
- Power Solutions



Everyone says their MCUs are ultra-low power. So what makes us different? Ultra-low power is in our DNA! MSP430 MCUs are designed from the ground up specifically for ultra-low-power applications.

Multiple low-power modes

The MSP430 MCU clock system has the ability to enable and disable various clocks and oscillators which allow the device to enter several low-power modes (LPMs). The flexible clocking system optimizes overall current consumption by only enabling the required clocks when appropriate. This means that MSP430 MCUs can operate for decades on a single coin cell battery.

Autonomous peripherals

Intelligent analog and digital peripherals can run autonomously in low-power modes. This allows our MCUs to operate as efficiently as possible.

Instant wakeup

The ultra-fast digitally controlled oscillator (DCO), with start-up times as fast as 1 μ s, allows MSP430-based systems to remain in low-power modes for the longest possible interval – extending battery life. The DCO is fully user programmable.

Real-time clock

The low-power real-time clock (RTC), available on select MSP430 MCUs, precisely keeps real time and enables wakeup at specified intervals. Some variants also include a switchable battery backup system that maintains operations when the primary power supply fails.

Direct memory access

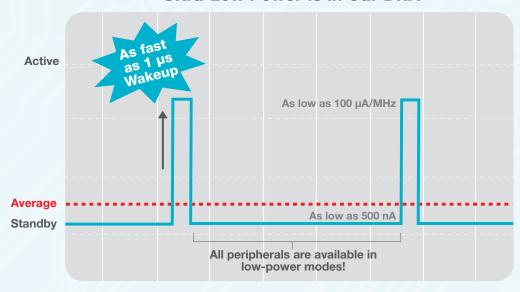
MSP430 MCUs also feature a direct memory access controller, enabling memory transfer with no CPU intervention. This means higher throughput of peripheral data and lower system power.

Embedded FRAM enables lowest power

- Industry-leading active power consumption (<100 µA/MHz)
- 250× less power than Flash writes
- Fast non-volatile writes

Learn more about MSP430 MCUs with embedded, non-volatile FRAM memory on page 10 or on the web at ti.com/fram

Ultra-Low Power is in Our DNA



Productive Low-Power Modes Allow:

- Take ADC samples
- Transfer data throughout memory range
- Output PWM signal
- Update LCD
- Send and receive serial communication

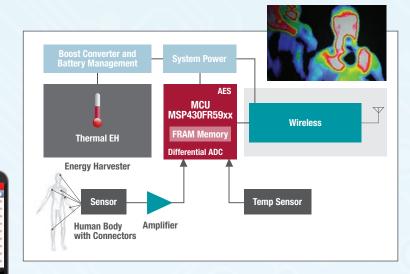
Integration

Did you know that our MCUs offer integration designed with your applications in mind? The 400+ MSP430 devices offer high-performance peripherals including USB, RF, LCD controllers and Sigma-Delta ADCs. This allows designers to find the appropriate MSP430 device for many low power applications. This integration enables solutions with smaller physical footprints and reduced bill of materials costs.

Energy Harvesting Sensor Network

The MSP430FR59xx MCU with FRAM technology can control wireless sensor networks by harnessing the body heat of the user

- Differential ADC connect directly to sensors and limit interference
- Industry-standard communication protocols
- AES module protect your important data



Application Processor 1.8 V PC SPI ADC MSP430F5229 Always On Co-Processor 1.8 V PC/SPI ADC Temperature Sensors TouchPad Inertial Sensors Fuel Gauge

Co-Processor for Smart Devices

The MSP430F52xx MCU can operate as an always on ultra-low-power co-processor to an applications processor. The MSP430 MCU can be used to offload functions such as sensor hub, keyboard control, battery and power management, capacitive touch, haptics and proximity detection.

 Split rail 1.8 V/3.3 V – directly connect to applications processors and sensors alike





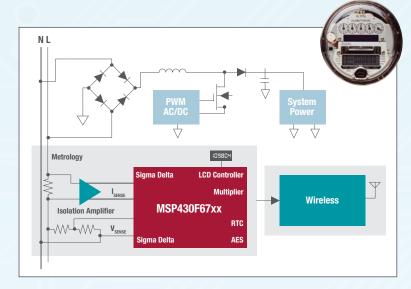


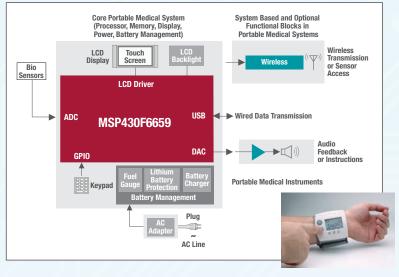
Our peripherals have been designed to give you maximum functionality and provide system-level interrupts, resets and bus arbitration at the lowest power. Many peripherals function autonomously, thereby minimizing CPU time spent in active mode. This means that MSP430 MCUs offer more performance with less power. The potential applications are endless!

Intelligent Utility Meter

The MSP430F67xx MCU is perfect for precisely measuring electricity usage.

- Up to 7 24-bit Sigma-Delta ADCs 2000:1 dynamic range
- Multiplier accelerate calculations
- RTC Module reliable meter readings
- Auxiliary power supply back up system support
- Meets or exceeds global regulatory requirements





Portable Medical Devices

The MSP430F6659 MCU has integrated peripherals to meet the needs of many portable medical applications.

- 512 KB Flash run virtually any wireless stack and enable over-the-air updates
- USB and LCD controllers
- 6 serial ports
- 16-channel, 12-bit ADC directly interface with analog sensors
- DAC drive speakers; generate bias for sensors







Ease of Use

Software

Our software ecosystem can help you tap into the ultra-low-power performance and intelligent peripherals of your MSP430 MCU. Support is available for a variety of professional and open-source integrated development environments. Using our complete suite of software tools, you can quicken time to market and maximize code efficiency. This means you can get started quicker with MSP430 MCUs!

Integrated Development Environments



TI's Code Composer Studio™ IDE: Free code-limited version



IAR Embedded Workbench®: Free code-limited version





MSPGCC and Energia: Free, open source, community driven and supported

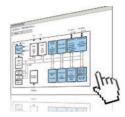
Software Support Tools



MSP430Ware[™] software: Driver library and a collection of code, data sheets and user guides



ULP Advisor™ software: Ensures code is optimized for ultra-low power



Grace[™] software: Easy-to-use GUI for enabling and configuring peripherals

Don't Forget to Check Out Our Royalty-Free Software Libraries

Peripheral Driver Library: Intuitive function calls for configuring and using integrated peripherals

Capacitive Touch Library: Support for buttons, sliders, wheels and proximity sensors. Touch Pro GUI now available to evaluate, diagnose and tune capacitive touch sensors.

Math Library: Newly optimized to increase performance in your applications

NFCLink: Quickly and easily create NFC applications for TRF79xx NFC transceivers using an MSP430 MCU

Energy Library: Designed for quick ramp-up in metering, smart grid, energy monitoring and home/building automation applications where precise measurements are essential.

SimpliciTI[™]: Open-source software for building a network with battery-operated devices when pairing an MSP430 MCU and a TI RF transceiver such as the CC1101.

Bluetooth® Stack: Software stack for standard profiles like SPP and GATT provided when pairing an MSP430 MCU with a TI *Bluetooth* transceiver such as the CC256x.

Get started now at ti.com/msp430tools

Hardware

Now, let's talk hardware! MSP430 MCUs are supported by a broad collection of hardware development tools for beginners as well as experienced engineers. Our tools range from low-cost development kits like the MSP430 LaunchPad Evaluation Kit to highly-integrated, application-specific platforms and target boards for integrating MSP430 into your designs.

MSP430 LaunchPad and BoosterPack Ecosystem

LaunchPad Evaluation Kits

provide customers everything needed to get started, at \$9.99.

Try it out with Energia for the simplified user experience! Learn more about this easy-to-use IDE at **energia.nu/**

BoosterPacks are plug-in modules for the LaunchPad, which enable customers to stack additional functionality such as wireless, capacitive touch and more.

Explore the ecosystem at

ti.com/launchpad

MSP-EXP430F5529LP connected to the CC3000-B00ST



Full-Featured Development Kits



eZ430-CHRONOS

CC430-based RF wireless development kit in a sports watch form factor in 433, 868 and 915 MHz frequencies **Price: \$58**



MSP-EXP430FG4618

Featuring MSP430FG4618 and MSP430F2013 on-board segmented display, buzzer, RS-232, capacitive touch, microphone, RF headers, JTAG

Price: \$117



MSP-EXP430F5529

Featuring MSP430F5529 complete USB development platform, on-board dot matrix display, JTAG, RF headers, on-board emulation, accelerometer, microSD, capacitive touch

Price: \$149



MSP-EXPCC430RF

Featuring CC430F6137 and CC430F5137 on-board emulation, segmented LCD, light sensor, includes F6137-based motherboard and F5137-based satellite board

Price: \$175

Hardware Support Tools

One tool to rule them all. The MSP430 Flash Emulation Tool (MSP-FET) supports all MSP430 devices when paired with the appropriate target board.



Production Programmer

The MSP-GANG can program up to eight identical MSP430 Flash or FRAM devices at the same time and allows the user to fully customize the process.



We're Here for You!

- Reference designs available for many applications
- Direct support through our E2E[™] Forum at ti.com/e2e-msp430

Learn more at ti.com/msp430tools

MSP430[™] MCUs and TI can scale with your applications. The MSP430 portfolio consists of over 400 devices ranging from the MSP430 Value Line to our revolutionary, highly integrated microcontrollers with embedded FRAM memory.

Series		UI	tra-Low Pow	ver		Low Power + Performance	Security Communicat	
	L09x				FRxx			
Part Number	Low Voltage	G2x/I2x	F1x	F2x/F4x	FRAM	F5x/6x	RF-430	CC430
Max speed (MHz)	4	16	16	16	24	25	4	20
NVM (max KB)	0	56	120	120	128	512	ROM Fixed Function	32
SRAM (max KB)	2	4	10	8	2	67	4	4
GPI0	11	4-32	10-48	14-80	17-40	29–90	Up to 8	30-44
Comparator	•	•	•	•	•	•	•	•
Timer	•	•	•	•	•	•	•	•
ADC	•	•	•	•	•	•	On select	•
DAC	•		•	•		•		
UART		•	•	•	•	•	•	•
l ² C		•	•	•	•	•	•	•
SPI		•	•	•	•	•	•	•
Capacitive touch		•			•			
Multiplier		•	•	•	•	•		•
DMA			•	•	•	•		•
Op amps			•	•				
LCD				•	•	•		•
RTC				•	•	•		•
PMM					•	•	•	•
1.8-V I/O						•		
CRC					•	•	•	•
High-resolution timer						•		
USB						•		
Hardware encryption (AES)					•	•		•
FRAM					•		On select	
RF							13.56 MHz (ISO 15693 or ISO 14443B interface)	Sub-1GH

Check out the other great products from TI and unlock the full potential of your applications:

Collect data

Sensors – The TMP006 sensor measures the temperature of an object without the need to make contact with the object.

ti.com/sensorproducts

Analog Front Ends – Devices like the LMP91000 bridge the gap between sensors and the MSP430 MCU which can significantly simplify a system.





Power the system

Power – TI offers regulators, fuel gauges, and battery monitors. The TPS709 linear drop out regulator can regulate voltage to the MCU, while devices such as the TPS3839 reset IC can accurately track battery activity to ensure the MSP430 MCU remains in a safe state.

ti.com/power

Transmit and receive data

Wireless – TI offers radios ranging from sub-1 GHz to Wi-Fi®. The CC1101 is a highly integrated RF transceiver for low-power wireless applications in the 315-/433-/868-/915-MHz ISM bands. Devices like the high-performance TRF7970 13.56-MHz transceiver enable low-power NFC solutions. The CC2564 paired with an MSP430 MCU offer a dual-mode solution for *Bluetooth*® connectivity. The CC3000 is a self-contained Wi-Fi solution that simplifies Internet connectivity. **ti.com/wireless**

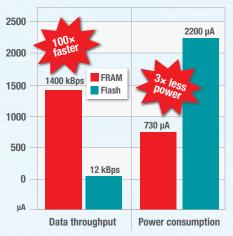


Technology	Hardware	Software	Additional information
NFC	TRF7970	NFCLink	ti.com/nfclink
Sub-1 GHz	CC1101	SimpliciTI™	ti.com/simpliciti
Bluetooth®/BLE	CC256x	Stonestreet One BT Stacks	ti.com/tool/stonestreetone-bt-sdk
Wi-Fi®	CC3000	SimpleLink	ti.com/simplelink
GPS	CC4000	SimpleLink	ti.com/simplelink

Device Catalog

FRAM: The Future of Embedded Memory

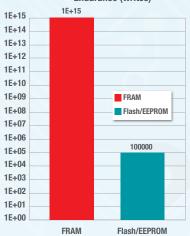
FRAM, or Ferroelectric Random Access Memory, is a non-volatile memory that combines the speed, ultra-low-power, endurance and flexibility of SRAM with the reliability and stability of Flash to combine program and data into one unified memory space for the lowest power and easiest-to-use microcontroller architecture. **ti.com/fram**

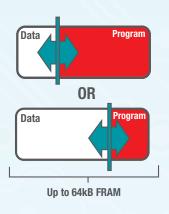


What does this mean for you?

- Lower power
- Faster data throughput
- Virtually unlimited write endurance
- Configurable as program or data memory







FR57x Performance Data

MSP430	FRA	M S <u>e</u>	ries -	- Up	to 2 <u>4</u>	MHz												
Part Number	FRAM (KB)	SRAM (B)	CPU Speed (MHz)	GPIO (max)	16-Bit Timers	Watchdog and RTC	PMM: BOR, SVS, SVM, LDO	l ² C	SPI	UART	DMA	MPY	Comp E	Temp Sensor	ADC Ch/Res	Additional Features [†]	Pin/Package	1 ku Price (U.S. S
FR2x																		
MSP430FR2032	8.5	1	16	60	2	•	•	2	1	2	_	_	_	•	14 ch ADC10	IR	TSS0P48/56, LQFP64/48	1.60
MSP430FR2033	15.5	2	16	60	2	•	•	2	1	2	_	_	_	•	14 ch ADC10	IR	TSS0P48/56, LQFP64/48	1.60
FR4x															_			
MSP430FR4131	4.5	0.5	16	60	2	•	•	2	1	2	_	_	_	•	14 ch ADC10	LCD, IR	TSS0P48/56, LQFP64/48	1.60
MSP430FR4132	8.5	1	16	60	2	•	•	2	1	2	_	_	_	•	14 ch ADC10	LCD, IR	TSS0P48/56, LQFP64/48	1.60
MSP430FR4133	15.5	2	16	60	2	•	•	2	1	2	_	_	_	•	14 ch ADC10	LCD, IR	TSS0P48/56, LQFP64/48	1.6
FR572x																	,	
MSP430FR5720	4	512	8	21	3	•	•	1	2	1	•	•	•	•	6 ch ADC10	MPU	24QFN, 28TSSOP	1.7
MSP430FR5721	4	512	8	32	5	•	•	1	3	2	•		•	•	14 ch ADC10	MPU	38TSSOP, 40QFN	1.8
MSP430FR5722	8	1024	8	21	3	•	•	1	2	1	•	•	•	•	6 ch ADC10	MPU	24QFN, 28TSSOP	1.8
MSP430FR5723	8	1024	8	32	5		•	1	3	2	•				_	MPU	38TSSOP, 40QFN	1.9
MSP430FR5724	8	1024	8	21	3	•	•	1	2	1	•	•	•	•	6 ch ADC10	MPU	24QFN, 28TSSOP	1.9
MSP430FR5725	8	1024	8	32	5	•	•	1	3	2	•	•		•	14 ch ADC10	MPU	38TSSOP, 40QFN	2.0
MSP430FR5726	16	1024	8	21	3	•	•	1	2	1	•	•	•	•	6 ch ADC10	MPU	24QFN, 28TSSOP	2.0
MSP430FR5727	16	1024	8	32	5	•	•	1	3	2	•		•	•	_	MPU	38TSSOP, 40QFN	2.2
MSP430FR5728	16	1024	8	21	3	•	•	1	2	1	•	•	•	•	6 ch ADC10	MPU	24QFN, 28TSSOP	2.1
MSP430FR5729	16	1024	8	32	5	•	•	1	3	2	•	•	•	•	14 ch ADC10	MPU	38TSSOP, 40QFN	2.1
FR573x																		
MSP430FR5730	4	512	24	21	3	•	•	1	2	1	•	•	•	•	6 ch ADC10	MPU	24QFN, 28TSSOP	1.9
MSP430FR5731	4	512	24	32	5	•	•	1	3	2	•	•	•	•	14 ch ADC10	MPU	38TSSOP, 40QFN	1.9
MSP430FR5732	4	1024	24	21	3	•	•	1	2	1	•	•	•	•	6 ch ADC10	MPU	24QFN, 28TSSOP	2.0
MSP430FR5733	8	1024	24	32	5			1	3	2					_	MPU	38TSSOP, 40QFN	2.0
MSP430FR5734	8	1024	24	21	3			1	2	1					6 ch ADC10	MPU	24QFN, 28TSSOP	2.1
MSP430FR5735	8	1024	24	32	5			1	3	2					14 ch ADC10	MPU	38TSSOP, 40QFN	2.2
MSP430FR5736	16	1024	24	21	3			1	2	1					6 ch ADC10	MPU	24QFN. 28TSSOP	2.1
MSP430FR5737	16	1024	24	32	5			1	3	2					_	MPU	38TSSOP, 40QFN	2.3
MSP430FR5738	16	1024	24	21	3			1	2	1					6 ch ADC10	MPU	24QFN, 28TSSOP	2.3
MSP430FR5739	16	1024	24	32	5			1	3	2					14 ch ADC10	MPU	38TSSOP, 40QFN	2.4

¹Prices are quoted in U.S. dollars and represent year 2014 suggested resale price.

*Represents number of capture/compare registers per timer.

New products are listed in bold red

1MPU: Memory Protection Unit is used for memory segmentation and access management for code protection. ESI represents extended scan interface which is an integrated dual analog front end.

Industry's Lowest Power MCU Platform

Ultra-low-leakage process technology

- Unique mixed-signal ultra-low-leakage process technology
- Enables variety of new low-power peripherals
- Consistent low power over entire temperature range

Unparalleled performance with unified FRAM

- World's lowest-power write to a non-volatile memory is 250× less energy per bit
- · Speed and flexibility of traditional RAM
- Near infinite endurance and 100% non-volatile

MSP430™ DNA evolved

- Continuing to pioneer the low-power landscape
- Leading power efficiency over entire system architecture
- Industry leading analog integration
- · Complete software package for easiest development



MSP430 F	RAN	l Ser	ies -	- Up	to 24	MHz (continu	ed)										
Part Number	FRAM (KB)	SRAM (B)	CPU Speed (MHz)	GPIO (max)	16-Bit Timers	Watchdog and RTC	PMM: BOR, SVS, SVM, LDO	I ² C	SPI	UART	DMA	MPY	Comp E	Temp Sensor	ADC Ch/Res	Additional Features†	Pin/Package	1 ku Price (U.S. \$)
FR58xx															40 1 10010	450	TOOODOO NOTINA	
MSP430FR5847	32	1	16	33	5	•	•	1	3	2	•	•	•	•	16 ch ADC12	AES	TSS0P38, VQFN40	2.05
MSP430FR58471	32	1	16	33	5	•	•	1	3	2	•	•	•	•	16 ch ADC12	AES	VQFN40	2.05
MSP430FR5848	48	2	16	33	5	•	•	1	3	2	•	•	•	•	16 ch ADC12	AES	TSS0P38, VQFN40	2.15
MSP430FR5849	64	2	16	33	5	•	•	1	3	2	•	•	•	•	16 ch ADC12	AES	TSS0P38, VQFN40	2.20
MSP430FR5857	32	1	16	33	5	•	•	1	3	2	•	•	•	•	16 ch ADC12	AES	TSS0P38, VQFN40	2.05
MSP430FR5858	48	2	16	33	5	•	•	1	3	2	•	•	•	•	16 ch ADC12	AES	TSS0P38, VQFN40	2.15
MSP430FR5859	64	2	16	33	5	•	•	1	3	2	•	•	•	•	16 ch ADC12	AES	TSS0P38, VQFN40	2.20
MSP430FR5867	32	1	16	40	5	•	•	1	3	2	•	•	•	•	18 ch ADC12	AES	VQFN48	2.20
MSP430FR58671	32	1	16	40	5	•	•	1	3	2	•	•	•	•	18 ch ADC12	AES	VQFN48	2.15
MSP430FR5868	48	2	16	40	5	•	•	1	3	2	•	•	•	•	18 ch ADC12	AES	VQFN48	2.30
MSP430FR5869	64	2	16	40	5	•	•	1	3	2	•	•	•	•	18 ch ADC12	AES	VQFN48	2.30
MSP430FR5887	64	2	16	48	5	•	•	2	4	2	•	•	•	•	12 ch ADC12	ESI, AES	LQFP64, VQFN64	4.19
MSP430FR5888	96	2	16	48	5	•	•	2	4	2	•	•	•	•	12 ch ADC12	ESI, AES	LQFP64, VQFN64	4.27
MSP430FR5889	128	2	16	48	5	•	•	2	4	2	•	•	•	•	12 ch ADC12	ESI, AES	LQFP64, VQFN64	4.35
MSP430FR58891	128	2	16	48	5	•	•	2	4	2	•	•	•	•	12 ch ADC12	ESI, AES	LQFP64, VQFN64	4.35
FR59xx																		
MSP430FR5947	32	1	16	33	5	•	•	1	3	2	•	•	•	•	16 ch ADC12	AES	TSS0P38, VQFN40	2.10
MSP430FR59471	32	1	16	33	5	•	•	1	3	2	•	•	•	•	16 ch ADC12	AES	VQFN40	2.10
MSP430FR5948	48	2	16	33	5	•	•	1	3	2	•	•	•	•	16 ch ADC12	AES	TSSOP38, VQFN40	2.20
MSP430FR5949	64	2	16	33	5	•	•	1	3	2	•	•	•	•	16 ch ADC12	AES	TSSOP38, VQFN40	2.25
MSP430FR5957	32	1	16	33	5	•	•	1	3	2	•	•	•	•	16 ch ADC12	AES	TSSOP38, VQFN40	2.10
MSP430FR5958	48	2	16	33	5	•	•	1	3	2	•	•	•	•	16 ch ADC12	AES	TSSOP38, VQFN40	2.20
MSP430FR5959	64	2	16	33	5	•	•	1	3	2	•	•	•	•	16 ch ADC12	AES	TSSOP38, VQFN40	2.25
MSP430FR5967	32	1	16	40	5	•	•	1	3	2	•	•	•	•	18 ch ADC12	AES	VQFN48	2.20
MSP430FR5968	48	2	16	40	5	•	•	1	3	2	•	•	•	•	18 ch ADC12	AES	VQFN48	2.25
MSP430FR5969	64	2	16	40	5	•	•	1	3	2	•	•	•	•	18 ch ADC12	AES	VQFN48	2.35
MSP430FR59691	64	2	16	40	5	•	•	1	3	2	•	•	•	•	18 ch ADC12	AES	VQFN48	2.35
MSP430FR5986	48	2	16	48	5		•	2	4	2	•	•	•	•	12 ch ADC12	ESI, AES	LQFP64, VQFN64	4.18
MSP430FR5987	64	2	16	48	5	•	•	2	4	2	•	•	•		12 ch ADC12	ESI, AES	LQFP64, VQFN64	4.24
MSP430FR5988	96	2	16	48	5			2	4	2	•	•	•	•	12 ch ADC12	ESI, AES	LQFP64, VQFN64	4.32
MSP430FR5989	128	2	16	48	5	•	•	2	4	2	•		•		12 ch ADC12	ESI, AES	LQFP64, VQFN64	4.40
MSP430FR59891	128	2	16	48	5			2	4	2					12 ch ADC12	ESI, AES	LQFP64, VQFN64	4.40

¹Prices are quoted in U.S. dollars and represent year 2014 suggested resale price.

^{*}Represents number of capture/compare registers per timer.

[†]MPU: Memory Protection Unit is used for memory segmentation and access management for code protection. ESI represents extended scan interface which is an integrated dual analog front end. New products are listed in **bold red**.

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Part Number	FRAM (KB)	SRAM (B)	CPU Speed (MHz)	GPIO (max)	16-Bit Timers	Watchdog and RTC	PMM: BOR, SVS, SVM, LDO	I ² C	SPI	UART	DMA	MPY	Comp E	Temp Sensor	ADC Ch/Res	Additional Features [†]	Pin/Package	1 ku Price (U.S. \$
FR68xx																		
MSP430FR6877	64	2	16	83	5	•	•	2	4	2	•	•	•	•	18 ch ADC12	LCD, AES	LQFP80, LQFP100	3.79
MSP430FR6879	128	2	16	83	5	•	•	2	4	2	•	•	•	•	18 ch ADC12	LCD, AES	LQFP80, LQFP100	3.95
MSP430FR68791	128	2	16	83	5	•	•	2	4	2	•	•	•	•	18 ch ADC12	LCD, AES	LQFP80, LQFP100	3.95
MSP430FR6887	64	2	16	83	5	•	•	2	4	2	•	•	•	•	18 ch ADC12	LCD, ESI, AES	LQFP80, LQFP100	4.29
MSP430FR6888	96	2	16	83	5	•	•	2	4	2	•	•	•	•	18 ch ADC12	LCD, ESI, AES	LQFP80, LQFP100	4.37
MSP430FR6889	128	2	16	83	5	•	•	2	4	2	•	•	•	•	18 ch ADC12	LCD, ESI, AES	LQFP80, LQFP100	4.45
MSP430FR68891	128	2	16	83	5	•	•	2	4	2	•	•	•	•	18 ch ADC12	LCD, ESI, AES	LQFP80, LQFP100	4.45
FR69xx																		
MSP430FR6927	64	2	16	52	5	•	•	2	4	2	•	•	•	•	18 ch ADC12	LCD, AES	LQFP64, VQFN64	3.79
MSP430FR69271	64	2	16	52	5	•	•	2	4	2	•	•	•	•	18 ch ADC12	LCD, AES	LQFP64, VQFN64	3.79
MSP430FR6928	96	2	16	52	5	•	•	2	4	2	•	•	•	•	18 ch ADC12	LCD, AES	LQFP64, VQFN64	3.87
MSP430FR6977	64	2	16	83	5	•	•	2	4	2	•	•	•	•	18 ch ADC12	LCD, AES	LQFP80, LQFP100	3.84
MSP430FR6979	128	2	16	83	5	•	•	2	4	2	•	•	•	•	18 ch ADC12	LCD, AES	LQFP80, LQFP100	4.00
MSP430FR69791	128	2	16	83	5	•	•	2	4	2	•	•	•	•	18 ch ADC12	LCD, AES	LQFP80, LQFP100	4.00
MSP430FR6987	64	2	16	83	5	•	•	2	4	2	•	•	•	•	18 ch ADC12	LCD, ESI, AES	LQFP80, LQFP100	4.34
MSP430FR6988	96	2	16	83	5	•	•	2	4	2	•	•	•	•	18 ch ADC12	LCD, ESI, AES	LQFP80, LQFP100	4.42
MSP430FR6989	128	2	16	83	5	•	•	2	4	2	•	•	•	•	18 ch ADC12	LCD, ESI, AES	LQFP80, LQFP100	4.50
MSP430FR69891	128	2	16	83	5	•	•	2	4	2	•	•	•	•	18 ch ADC12	LCD, ESI, AES	LQFP80, LQFP100	4.50

¹Prices are quoted in U.S. dollars and represent year 2014 suggested resale price.

^{*}Represents number of capture/compare registers per timer.

†MPU: Memory Protection Unit is used for memory segmentation and access management for code protection. ESI represents extended scan interface which is an integrated dual analog front end.

New products are listed in **bold red**.

Value Line

High performance for cost-sensitive applications

The MSP430G2xx 16-bit microcontroller features Flash-based ultra-low-power MCUs up to 16 MIPS with 1.8V - 3.6V operation. Includes the very-low power oscillator (VLO), internal pull-up/pull-down resistors and low-pin-count options.

Device parameters

Flash options: 0.5 KB – 56 KB
RAM options: 128 B – 4 KB
GPIO options: 10, 16, 24, 32 pins

• ADC options: Slope, 10-bit SAR

• Other integrated peripherals: Capacitive Touch I/O (CT), High Frequency Oscillator (HF)

MSP4300	JEAN	Tail	C LII			op i	O TO IVII	-		HOOL						
art Number	Flash (KB)	SRAM (B)	I/O (max)	Total	Timers A [*]	B.	Watchdog and RTC	BOR	USI: I ² C/SPI	USCI: I ² C/SPI/ UART	Comp_A+	Temp Sensor	ADC Ch/Res	Additional Features	Packages	1ku Price (U.S.
G2xx0																
/ISP430G2210	2	128	4	1	2	_	•		_	_		_	Slope	_	8SOIC	0.3
MSP430G2230	2	128	4	1	2	_	•	•	•	_	_	•	4 ch ADC10	_	8SOIC	0.4
2xx1																
1SP430G2001	0.5	128	10	1	2	_	•	•	_	_	_	_	_	_	14TSSOP, N; 16QFN	0.3
MSP430G2101	1	128	10	1	2	_			_	_	_	_	_	_	14TSSOP, N; 16QFN	0.4
MSP430G2121	1	128	10	1	2	_			•	_	_	_	_	_	14TSSOP, N: 16QFN	0.4
MSP430G2201	2	128	10	1	2	_				_	_	_	_	_	14TSSOP, N; 16QFN	0.4
MSP430G2221	2	128	10	1	2	_			•	_	_	_	_	_	14TSSOP, N; 16QFN	0.4
MSP430G2111	1	128	10	1	2	_					•		Slope		14TSSOP, N; 16QFN	0.4
ASP430G22111	2	128	10	1	2				_	_		_	Slope		14TSSOP, N; 16QFN	0.4
							_		_	_		_		_	, ,	
MSP430G2131	1	128	10	1	2	_	•	•	•	_	_	•	8 ch ADC10	_	14TSSOP, N; 16QFN	0.4
MSP430G2231	2	128	10	1	2		•	•	•			•	8 ch ADC10		14TSSOP, N; 16QFN	0.5
i2xx2																
/ISP430G2102	1	256	16	1	3	-	•	•	•	_	_	_	_	CT	14TSSOP; 20TSSOP, N; 16QFN	0.4
/ISP430G2202	2	256	16	1	3	_	•	•	•	_	_	_	-	CT	14TSSOP; 20TSSOP, N; 16QFN	0.5
/ISP430G2302	4	256	16	1	3	_	•		•	_	_	_	_	CT	14TSSOP; 20TSSOP, N; 16QFN	0.5
/ISP430G2402	8	256	16	1	3	_	•	•	•	_	_	_	_	CT	14TSSOP; 20TSSOP, N; 16QFN	0.6
MSP430G2112	1	256	16	1	3	_	•	•	•	_	•	_	Slope	CT	14TSSOP; 20TSSOP, N; 16QFN	0.4
/ISP430G2212	2	256	16	1	3	_	•	•	•	_	•	_	Slope	CT	14TSSOP; 20TSSOP, N; 16QFN	0.5
ISP430G2312	4	256	16	1	3	_	•	•	•	_	•	_	Slope	CT	14TSSOP; 20TSSOP, N; 16QFN	0.6
NSP430G2412	8	256	16	1	3	_				_		_	Slope	CT	14TSSOP; 20TSSOP, N; 16QFN	0.6
ISP430G2132	1	256	16	1	3	_				_	_	•	8 ch ADC10	CT	14TSSOP; 20TSSOP, N; 16QFN	0.5
ISP430G2232	2	256	16	1	3	_				_	_		8 ch ADC10	CT	14TSSOP; 20TSSOP, N; 16QFN	0.5
ISP430G2332	4	256	16	1	3	_				_	_		8 ch ADC10	CT	14TSSOP; 20TSSOP, N; 16QFN	0.6
MSP430G2432	8	256	16	1	3	_					_		8 ch ADC10	CT	14TSSOP; 20TSSOP, N; 16QFN	0.7
MSP430G2152	1	256	16	1	3	_					•		8 ch ADC10	CT	14TSSOP; 20TSSOP, N; 16QFN	0.5
ASP430G2252	2	256	16	1	3					_			8 ch ADC10	CT	14TSSOP: 20TSSOP, N; 16QFN	0.6
MSP430G2352		256	16	1	3					_			8 ch ADC10	CT	, , ,	0.6
	4					_	•		_			_			14TSSOP; 20TSSOP, N; 16QFN	
ISP430G2452	8	256	16	1	3	_	•	•	•	_	•	•	8 ch ADC10	CT	14TSSOP; 20TSSOP, N; 16QFN	0.7
E2xx3		0=0	0.1											0.7	2070000 H 2070000 2005H	
ASP430G2203	2	256	24	2	3	-	•	•	_	•	_	_		CT	20TSSOP, N; 28TSSOP; 32QFN	0.6
MSP430G2303	4	256	24	2	3	_	•	•	_	•	_	_	_	CT	20TSSOP, N; 28TSSOP; 32QFN	0.6
MSP430G2403	8	512	24	2	3	_	•	•	_	•	_	_	_	CT	20TSSOP, N; 28TSSOP; 32QFN	0.7
/ISP430G2213	2	256	24	2	3	_	•	•	_	•		_	Slope	CT	20TSSOP, N; 28TSSOP; 32QFN	0.6
/ISP430G2313	4	256	24	2	3	_	•	•	_			_	Slope	CT	20TSSOP, N; 28TSSOP; 32QFN	0.6
ISP430G2413	8	512	24	2	3	_	•	•	_	•	•	_	Slope	CT	20TSSOP, N; 28TSSOP; 32QFN	0.7
ISP430G2513	16	512	24	2	3	_	•	•	_	•	•	_	Slope	CT	20TSSOP, N; 28TSSOP; 32QFN	0.9
MSP430G2133	1	256	24	2	3	_		•	_	•	_	•	8 ch ADC10	CT	20TSSOP, N; 28TSSOP; 32QFN	_
ISP430G2233	2	256	24	2	3	_			_		_	•	8 ch ADC10	CT	20TSSOP, N: 28TSSOP: 32QFN	0.6
ISP430G2333	4	256	24	2	3	_			_		_		8 ch ADC10	CT	20TSSOP, N; 28TSSOP; 32QFN	0.6
ISP430G2433	8	512	24	2	3	_			_		_		8 ch ADC10	CT	20TSSOP, N; 28TSSOP; 32QFN	0.7
ISP430G2533	16	512	24	2	3	_			_		_		8 ch ADC10	CT	20TSSOP, N; 28TSSOP; 32QFN	0.7
ISP430G2333	1	256	24	2	3						<u> </u>		8 ch ADC10	CT	20TSSOP, N; 28TSSOP; 32QFN	0.8
	2															
ISP430G2253		256	24	2	3	_		•	_	•			8 ch ADC10	CT	20TSSOP, N; 28TSSOP; 32QFN	0.6
ISP430G2353	4	256	24	2	3	_		•	_	•	•	•	8 ch ADC10	CT	20TSSOP, N; 28TSSOP; 32QFN	0.7
ISP430G2453	8	512	24	2	3	_	•	•	_	•	•	•	8 ch ADC10	CT	20TSSOP, N; 28TSSOP; 32QFN	0.8
ISP430G2553	16	512	24	2	3	_	•	•	_	•	•	•	8 ch ADC10	CT	20TSSOP, N; 28TSSOP; 32QFN	0.9
2xx4																
/ISP430G2444	8	512	32	2	3	3	•	•	_	•	_	•	12 ch ADC10	HF	38TSSOP, 40QFN, 49DSBGA	1.0
/ISP430G2544	16	512	32	2	3	3	•	•	_	•	_	•	12 ch ADC10	HF	38TSSOP, 40QFN, 49DSBGA	1.1
/ISP430G2744	32	1024	32	2	3	3	•	•	_	•	_	•	12 ch ADC10	HF	38TSSOP, 40QFN, 49DSBGA	1.1
2xx5																
ASP430G2755	32	4094	32	3	3	3	•	•	_	•	•	•	12 ch ADC10	CT, HF	38TSSOP, 40QFN	1.2
/ISP430G2855	48	4094	32	3	3	3			_				12 ch ADC10	CT, HF	38TSSOP, 40QFN	1.2
ISP430G2955	56	4094	32	3	3	3	-			_	_	-	12 ch ADC10	CT, HF	00.0001, 104111	1.3

^{*}Represents number of capture/compare registers per timer.

Device Catalog

F - Family

Ultra-low power with increased integration and performance

Our largest family of devices, offers ultra-low power with options featuring unmatched analog and digital integration.

Device parameters

• Up to 25 MHz

Flash options: 0.5 KB – 512 KB
RAM options: 128 B – 64 KB
GPIO options: Up to 90 pins

				Ė	Timers													41 81
Doub Museubou	Flash	SRAM	1/0	_		B,	Watchdog	DOD	CVC	USART	DMA	MDV	Comm. A	Temp	ADC	Additional	Deelro vo (o)	1 ku Pri
Part Number	(KB)	(B)	(max)	Total	A*	В	and RTC	BUK	SVS	(UART/SPI)	DIMA	MPY	Comp_A	Sensor	Ch/Res	Features	Package(s)	(U.S. \$
F11x1																		
MSP430F1101A	1	128	14	1	3	_	•	_	_	_	_	_	•	_	Slope	_	20TVSOP, SOIC, TSSOP; 24QFN	1.06
MSP430F1111A	2	128	14	1	3	_	•	_	_	_	_	_	•	_	Slope	_	20TVSOP, SOIC, TSSOP; 24QFN	1.22
MSP430F1121A	4	256	14	1	3	_	•	_	_	_	_	_	•	_	Slope	_	20TVSOP, SOIC, TSSOP; 24QFN	1.56
F11x2																		
MSP430F1122	4	256	14	1	3	_	•	•	_		_		_	•	5 ch ADC10	_	20SOIC, TSSOP: 32QFN	1.67
MSP430F1132	8	256	14	1	3	_		•	_	_	_	_	_		5 ch ADC10	_	20SOIC, TSSOP; 32QFN	1.78
F12x																	,,	
MSP430F122	4	256	22	1	3					1			•	_	Slope	_	28SOIC, TSSOP; 32QFN	1.67
MSP430F122	8	256	22	1	3				_	1				_	Slope		28SOIC, TSSOP; 32QFN	1.72
F12x2	U	200	22		J										οιυμο		ZOOUIO, TOOUI , OZQEN	1.72
		0.50													0 1 100/-		000010 70000 0057::	,
MSP430F1222	4	256	22	1	3	_	•	•	_	1	_	_	_	•	8 ch ADC10	_	28SOIC, TSSOP; 32QFN	1.72
MSP430F1232	8	256	22	1	3	_	•	•	_	1	_			•	8 ch ADC10	_	28SOIC, TSSOP; 32QFN	1.83
F13x																		
MSP430F133	8	256	48	2	3	3	•	_	_	1	_	_	•	•	8 ch ADC12	_	64LQFP, TQFP, QFN	2.94
MSP430F135	16	512	48	2	3	3	•	_	_	1	_	_	•		8 ch ADC12	_	64LQFP, TQFP, QFN	3.28
F13x1																		
MSP430F1331	8	256	48	2	3	3	•	_	_	1	_		•	_	Slope	_	64LQFP, QFN	_
MSP430F1351	16	512	48	2	3	3		_	_	1	_	_		_	Slope	_	64LQFP, QFN	_
F14x																	, .	
MSP430F147	32	1024	48	2	3	7	•	_	_	2	_	16×16	•	•	8 ch ADC12		64LQFP, TQFP, QFN	4.00
MSP430F148	48	2048	48	2	3	7		_	_	2	_	16×16			8 ch ADC12	_	64LQFP, TQFP, QFN	4.33
MSP430F149	60	2048	48	2	3	7		_	_	2	_	16×16			8 ch ADC12	_	64LQFP, TQFP, QFN	4.66
MSP430F1471	32	1024	48	2	3	7		_	_	2	_	16×16			Slope	_	64LQFP, QFN	4.55
MSP430F1481	48	2048	48	2	3	7		_	_	2	_	16×16		_	Slope	_	64LQFP, QFN	5.11
MSP430F1491	60	2048	48	2	3	7	•	_	_	2	_	16×16		_	Slope	_	64LQFP, QFN	5.11
F15x																	,	
MSP430F155	16	512	48	2	3	3				1 with I ² C			•	•	8 ch ADC12	(2) DAC12	64LQFP, QFN	5.38
MSP430F155	24	1024	48	2	3	3				1 with I ² C					8 ch ADC12	(2) DAC12	64LQFP, QFN	5.61
MSP430F157	32	1024	48	2	3	3				1 with I ² C					8 ch ADC12	(2) DAC12	64LQFP, QFN	5.95
F16x	UL	1027	TU		0	J				i wiui i U				_	O UII ADUIZ	(L) DAUIZ	OTEGII, GIN	0.30
		400:	- 10							0 111 100		10.1-			0 1 100/-	(0) DAO: -	0.11.050.0511	
MSP430F167	32	1024	48	2	3	7	•	•	•	2 with I ² C	•	16×16	•	•	8 ch ADC12	(2) DAC12	64LQFP, QFN	6.88
MSP430F168	48	2048	48	2	3	7	•	•	•	2 with I2C	•	16×16	•	•	8 ch ADC12	(2) DAC12	64LQFP, QFN	7.61
MSP430F169	60	2048	48	2	3	7		•	•	2 with I2C	•	16×16	•	•	8 ch ADC12	(2) DAC12	64LQFP, QFN	8.16
MSP430F1610	32	5120	48	2	3	7	•	•	•	2 with I ² C	•	16×16	•	•	8 ch ADC12	(2) DAC12	64LQFP, QFN	8.72
MSP430F1611	48	10240	48	2	3	/	•	•	•	2 with I ² C	•	16×16	•	•	8 ch ADC12	(2) DAC12	64LQFP, QFN	9.16
MSP430F1612	55	5120	48	2	3	7	•		•	2 with I ² C		16×16	•		8 ch ADC12	(2) DAC12	64LQFP, QFN	9.5

¹Prices are quoted in U.S. dollars and represent year 2014 suggested resale price.

^{*}Represents number of capture/compare registers per timer.

Analog Fr	ont Er	nd (MS	P430A	FE2	(x) S	Seri	es – Up	to 1	2 MH	z						
				1	imers											1 ku
Part Number	Flash (KB)	SRAM (B)	I/O (max)	Total	٨٠	R*	Watchdog and RTC	BOR	svs	USART (UART/SPI)	MPY	Temp Sensor	ADC Ch/Res	Additional Features	Package(s)	Price ¹ (U.S. \$)
AFE2xx	(IVD)	(6)	(illax)	Total	^	_	and mo	Don	010	(UAITI/OI I)	I WII I	3011301	011/1103	1 catalos	i ackage(3)	(0.3. 9)
MSP430AFE221	4	256	11	1	3	_	•	•	•	•	•	•	(1) SD24	_	24TSSOP	1.80
MSP430AFE222	4	256	11	1	3	_	•	•	•	•	•	•	(2) SD24	_	24TSSOP	1.95
MSP430AFE223	4	256	11	1	3	_	•	•	•	•	•	•	(3) SD24	_	24TSSOP	2.10
MSP430AFE231	8	512	11	1	3	_	•	•	•	•	•	•	(1) SD24	_	24TSSOP	1.85
MSP430AFE232	8	512	11	1	3	_	•	•		•	•	•	(2) SD24	_	24TSSOP	2.00
MSP430AFE233	8	512	11	1	3	_	•	•	•	•	•	•	(3) SD24	_	24TSSOP	2.10
MSP430AFE251	16	512	11	1	3	_	•	•		•	•		(1) SD24	_	24TSSOP	1.90
MSP430AFE252	16	512	11	1	3	_	•	•		•	•	•	(2) SD24	_	24TSSOP	2.05
MSP430AFE253	16	512	11	1	3	_	•	•		•	•		(3) SD24	_	24TSSOP	2.20

¹Prices are quoted in U.S. dollars and represent year 2014 suggested resale price.

MSP430	FZX)	(Sei	ies -	_			VINE													
Part Number	Flash (KB)	SRAM (B)	I/O (max)	Total	imers A [*]	B [*]	Watchdog and RTC	BOR	svs	USI: (I ² C/SPI)	Ch A: UART/LIN/ Irda/SPI	Ch B: 1 ² C/SPI	DMA	MPY	Comp_A+	Temp Sensor	ADC Ch/Res	Additional Features	Package(s)	1 kı Price (U.S.
-20xx																			•	
MSP430F2001	1	128	10	1	2	_	•	•	Τ_	_	_	_	_	_	•	_	Slope	105 °C	14TSSOP, DIP; 16QFN	0.4
MSP430F2011	2	128	10	1	2	_	•	•	_	_	_	_	_	_		_	Slope	105 °C	14TSSOP, DIP; 16QFN	0.5
MSP430F2002	1	128	10	1	2	_	•	•	_	•	_	_	_	_	_	•	8 ch ADC10	105 °C	14TSSOP, DIP; 16QFN	0.6
MSP430F2012	2	128	10	1	2	_	•	•	_	•	_	_	_	_	_	•	8 ch ADC10	105 °C	14TSSOP, DIP; 16QFN	0.8
MSP430F2003	1	128	10	1	2	_	•	•	_	•	_	_	_	_	_	•	4 ch, SD16_A	105 °C	14TSSOP, DIP; 16QFN	0.9
MSP430F2013	2	128	10	1	2	_	•	•	_	•	_	_	_	_	_	•	4 ch, SD16_A	105 °C	14TSSOP, DIP; 16QFN	1.1
-21xx																				
MSP430F2101	1	128	16	1	3	_	•	•	T-	_	_	_	_	_	•	_	Slope	105 °C	20TVSOP, SOIC, TSSOP; 24QFN	0.6
MSP430F2111	2	128	16	1	3	_	•	•	_	_	_	_	_	_	•	_	Slope	105 °C	20TVSOP, SOIC, TSSOP; 24QFN	0.7
MSP430F2121	4	256	16	1	3	_	•	•	_	_	_	_	_	_	•	_	Slope	105 °C	20TVSOP, SOIC, TSSOP; 24QFN	0.9
MSP430F2131	8	256	16	1	3	_	•	•	_	_	_	_	_	_	•	_	Slope	105 °C	20TVSOP, SOIC, TSSOP; 24QFN	
MSP430F2112	2	256	22	2	3, 2	_	•	•	_	_	1	1	_	_	•	•	8 ch ADC10	105 °C	28TSSOP; 32QFN, QFN	1.1
MSP430F2122	4	512	22	2	3, 2	_	•	•	_	_	1	1	_	_	•	•	8 ch ADC10	105 °C	28TSSOP; 32QFN, QFN	1.4
MSP430F2132	8	512	22	2	3, 2	_	•	•	_	_	1	1	_	_	•	•	8 ch ADC10	105 °C	28TSSOP; 32QFN, QFN	1.5
22x2																				
MSP430F2232	8	512	32	2	3	3	•	•	_	_	1	1	_	_	_	•	12 ch ADC10	105 °C	38TSSOP; 40QFN; 49DSBGA	1.6
MSP430F2252	16	512	32	2	3	3	•	•	_	_	1	1	_	_	_	•	12 ch ADC10	105 °C	38TSSOP; 40QFN; 49DSBGA	1.9
MSP430F2272	32	1024	32	2	3	3	•	•	_	_	1	1	_	_	_	•	12 ch ADC10	105 °C	38TSSOP; 40QFN; 49DSBGA	2.0
-22x4																				
MSP430F2234	8	512	32	2	3	3	•	•	_	_	1	1	_	_	_	•	12 ch ADC10	(2) OPAMP, 105 °C	38TSSOP; 40QFN; 49DSBGA	1.8
MSP430F2254	16	512	32	2	3	3	•	•	_	_	1	1	_	_	_	•	12 ch ADC10	(2) OPAMP, 105 °C	38TSSOP; 40QFN; 49DSBGA	2.1
MSP430F2274	32	1024	32	2	3	3	•	•	-	_	1	1	_	-	_	•	12 ch ADC10	(2) OPAMP, 105 °C	38TSSOP; 40QFN; 49DSBGA	2.2
-23x0																				
MSP430F2330	8	1024	32	2	3	3	•	•	Τ_	_	1	1	_	16×16	•	_	Slope	105 °C	40QFN; 49DSBGA	1.6
MSP430F2350	16	2048	32	2	3	3	•	•	_	_	1	1	_	16×16	•	_	Slope	105 °C	40QFN; 49DSBGA	1.8
MSP430F2370	32	2048	32	2	3	3	•	•	_	_	1	1	_	16×16	•	_	Slope	105 °C	40QFN; 49DSBGA	1.9
-23x																				
MSP430F233	8	1024	48	2	3	3	•			_	1	1	_	16×16	•	•	8 ch ADC12	105 °C	64LQFP, QFN	2.1
MSP430F235	16	2048	48	2	3	3				_	1	1	_	16×16			8 ch ADC12	105 °C	64LQFP, QFN	2.6
-24x/10	10	2040	10														OUINDOIL	100 0	OTEGII, GIN	2.0
MSP430F247	32	4096	48	2	3	7	•	•	•	_	2	2	_	16×16	•	•	8 ch ADC12	105 °C	64LQFP, QFN	2.7
MSP430F248	48	4096	48	2	3	7	•	•	•	_	2	2	_	16×16	•	•	8 ch ADC12	105 °C	64LQFP, QFN	3.4
MSP430F249	60	2048	48	2	3	7	•	•	•	_	2	2	_	16×16	•	•	8 ch ADC12	105 °C	64LQFP, QFN	3.7
MSP430F2410	56	4096	48	2	3	7	•	•	•	_	2	2	_	16×16	•	•	8 ch ADC12	105 °C	64LQFP, QFN	4.6
-24x1																				
MSP430F2471	32	4096	48	2	3	7	•	•	•	_	2	2	_	16×16	•	_	Slope	105 °C	64LQFP, QFN	3.1
MSP430F2481	48	4096	48	2	3	7					2	2		16×16		_	Slope	105 °C	64LQFP, QFN	3.0
VISP430F2491	60	2048	48	2	3						2	2		16×16		_	Slope	105 °C	64LQFP, QFN	3.8
241x	00	2070	TU	-	U	,					-	_		10/10			оюрь	100 0	o rewrit, will	0.0
	00	4000	40/04			-					_	_		10.10			0 -1- 40040	105.00	C41 OFD, 001 OFD, 440DC1	
MSP430F2416	92	4096	48/64	2	3	7	•	•	•	_	2	2		16×16		•	8 ch ADC12	105 °C	64LQFP; 80LQFP; 113BGA	4.7
MSP430F2417	92	8192	48/64	2	3	7	•	•	•	_	2	2	_	16×16		•	8 ch ADC12	105 °C	64LQFP; 80LQFP; 113BGA	4.8
MSP430F2418	116	8192	48/64	2		7	•	•	•	-	2	2	_	16×16		•	8 ch ADC12	105 °C	64LQFP; 80LQFP; 113BGA	5.0
MSP430F2419	120	4096	48/64	2	3	7	•	•	•	_	2	2	_	16×16	•	•	8 ch ADC12	105 °C	64LQFP; 80LQFP;113BGA	5.3
261x																				
MSP430F2616	92	4096	48/64	2	3	7	•	•	•	_	2	2	•	16×16	•	•	8 ch ADC12	(2) DAC12, 105 °C	64LQFP; 80LQFP; 113BGA	5.8
MSP430F2617	92	8192	48/64	2	3	7	•	•	•	_	2	2	•	16×16	•	•	8 ch ADC12	(2) DAC12, 105 °C	64LQFP; 80LQFP; 113BGA	6.0
MSP430F2618	116	8192	48/64	2	3	7	•	•	•	_	2	2	•	16×16	•	•	8 ch ADC12	(2) DAC12, 105 °C	64LQFP; 80LQFP; 113BGA	6.3
MSP430F2619	120	4096	48/64	2	3	7	•	•	•	_	2	2	•	16×16	•	•	8 ch ADC12	(2) DAC12, 105 °C	64LQFP; 80LQFP; 113BGA	6.6

MSP430	F4xx	(Sei	ries	– U	Jp t	o 1	6 MHz	wi	th L	CD												
				1	imers						USC	ı						OD!!				11
		SRAM	1/0				Watchdog		0110	USART	Ch A: UART/LIN/	Ch B:	LCD				Temp	CPU Speed	ADC	Additional	.	Pri
Part Number F41x	(KB)	(B)	(max)	Total	A*	B*	and RTC	BOR	SVS	(UART/SPI)	IrDA/SPI	I ² C/SPI	Segments	DMA	MPY (Comp_A	Sensor	(MIPS)	Ch/Res	Features	Package(s)	(U.S
MSP430F412	4	256	48	1	3	_	•	•	•		_	_	96	_	_	•	_	8	Slope	_	64LQFP, QFN	1.
MSP430F413	8	256	48	1	3	_	•	•	•	_	_	_	96	_	_	•	_	8	Slope	_	64LQFP, QFN	1.
MSP430F415	16	512	48	2	3, 5	_	•	•	•	_	_	_	96	_	_ 1	•	_	8	Slope	_	64LQFP, QFN	1.
MSP430F417	32	1024	48	2	3, 5	_	•	•	•	_	_	_	96	_	_	•	_	8	Slope	_	64LQFP, QFN	1.
F41x2																						
MSP430F4132	8	512	56	2	3, 5	_	•	•	•	_	1	1	144	_	_	•	•	8	8 ch ADC10	_	48QFN; 64LQFP	1.
MSP430F4152	16	512	56	2	3, 5	_	•	•	•	_	1	1	144	_	_	•	•	8	8 ch ADC10	_	48QFN; 64LQFP	1.
-42x	-		-												_							
MSP430F423A	8	256	14	1	3	_	•	•		1	_	_	128	_	16×16	_	•	8	(3) SD16	_	64LQFP	2.
MSP430F425A	16	512	14	1	3	_				1	_	_	128	_	16×16	_		8	(3) SD16	_	64LQFP	2.
MSP430F427A	32	1024	14	1	3	_		•		1	_	_	128	_	16×16	_		8	(3) SD16	_	64LQFP	2.
W42x		1021		Ė				Ť	Ň				120		101110		_		(0) 02.10		0.120,11	
MSP430FW423	8	256	48	2	3, 5	_	•	•		_			96	_				8	Slope	SCAN IF	64LQFP	2.
WSP430FW425	16	512	48	2	3, 5	_				_	_	_	96	_	_			8	Slope	SCAN IF	64LQFP	2.
WSP430FW427	32	1024	48	2	3, 5	_				_	_		96	_	_		_	8	Slope	SCAN_IF	64LQFP	3.
MSP430FW428	48	2048	48	2	3, 5	_				_	_	_	96	_	_		_	8	Slope	SCAN_IF	64LQFP	3.
MSP430FW429	60	2048	48	2	3, 5					_	_	_	96	_	_	•	_	8	Slope	SCAN IF	64LQFP	3.
E42x					-, -			ň											опро			
MSP430FE423A	8	256	14	1	3	_				1	_	_	128	_	16×16	_	_	8	(3) SD16	ESP430	64LQFP	3.
MSP430FE425A	16	512	14	1	3	_				1	_	_	128	_	16×16	_	_	8	(3) SD16	ESP430	64LQFP	5.
VISP430FE427A	32	1024	14	1	3					1	_		128	_	16×16	_		8	(3) SD16	ESP430	64LQFP	4.
MSP430FE4232	8	256	14	1	3					1			128	_	16×16			8	(2) SD16	ESP430	64LQFP	2.
VISP430FE4242	12	512	14	1	3	_				1	_	_	128	_	16×16			8	(2) SD16	ESP430	64LQFP	2.
MSP430FE4252	16	512	14	1	3	_				1	_	_	128	_	16×16	_	_	8	(2) SD16	ESP430	64LQFP	2.
MSP430FE4272	32	1024	14	1	3	_				1	_	_	128	_	16×16	_	_	8	(2) SD16	ESP430	64LQFP	2.
42x0		1021						ň					120		1010				(2) 02 10	201 100	012011	
MSP430F4250	16	256	32	1	3				_		_	_	56	_	_	_	_	8	5 ch, SD16_A	DAC12	48SSOP, QFN	3.
MSP430F4260	24	256	32	1	3	_			_	_	_	_	56	_	_	_	_	8	5 ch, SD16_A	DAC12	48SSOP, QFN	3.
MSP430F4270	32	256	32	1	3	_		•	_	_	_	_	56	_	_	_	_	8	5 ch, SD16 A	DAC12	48SSOP, QFN	3.
FG42x0																						
MSP430FG4250	16	256	32	1	3	_	•	•	_	_	_	_	56	_	_	_	•	8	5 ch, SD16_A	DAC12, (2) OPAMP	48SSOP, QFN	3.
MSP430FG4260	24	256	32	1	3	_	•	•	_	_	_	_	56	_	_	_	•	8	F - L OD40 A	DAC12.	48SSOP. QFN	3.
MSP430FG4270	32	256	32	1	3								56						5 ch, SD16_A	(2) OPAMP DAC12,	48SSOP, QFN	4.
	32	200	32		3	_		_	_				30	_				0	3 GI, 3D 10_A	(2) OPAMP	4000UF, UFIN	4.
-43x																						
MSP430F435	16	512	48	2	3	3	•	•	•	1	_	_	128/160	-	_	•	•	8	8 ch ADC12	_	80LQFP; 100LQFP	
MSP430F436	24	1024	48	2	3	3	•			1	_	_	128/160	_	_			8	8 ch ADC12	_	80LQFP; 100LQFP	
MSP430F437	32	1024	48	2	3	3	•	•	•	1	_	_	128/160	_	_	•	•	8	8 ch ADC12	_	80LQFP; 100LQFP	
MSP430F438	48	2048	48	2	3	3	•	•	•	1	_	_	128	•	_	•	•	8	8 ch ADC12	_	80LQFP	5.
MSP430F439	60	2048	48	2	3	3	•	•	•	1	_	_	128	•	_	•	•	8	8 ch ADC12	_	80LQFP	5.
43x1																						
MSP430F4351	16	512	48	2	3	3	•	•	•	1	_	_	128/160	_	_	•	_	8	Slope	_	80LQFP; 100LQFP	2.
MSP430F4361	24	1024	48	2	3	3	•	•	•	1	_	_	128/160	_	_	•	_	8	Slope	_	80LQFP; 100LQFP	3.
MSP430F4371	32	1024	48	2	3	3	•	•	•	1	_	_	128/160	_	_	•	_	8	Slope	_	80LQFP; 100LQFP	3.
G43x																						
MSP430FG437	32	1024	48	2	3	3	•	•	•	1	_	_	128	•	_	•	•	8	12 ch ADC12	(2) DAC12,	80LQFP	3.
MSP430FG438	48	2048	48	2	3	3				1	_		128					8	10 ab ADC10	(3) OPAMP (2) DAC12,	80LQFP	4.
											_	_						0	12 OII ADO 12	(3) OPAMP (2) DAC12,		
WSP430FG439	60	2048	48	2	3	3	•	•	•	1	_	_	128	•	_	•	•	8	12 ch ADC12	(3) OPAMP	80LQFP	5.
-44x																						
MSP430F4481	48	2048	48	2	3	7	•	•	•	2	_	_	160		16×16	•	_	8	_	_	100LQFP	4.
MSP430F4491	60	2048	48	2	3	7	•	•	•	2	_	_	160		16×16	•	_	8	_	_	100LQFP	4.
VISP430F447	32	1024	48	2	3	7	•	•	•	2	_	_	160		16×16	•	•	8	8 ch ADC12	_	100LQFP	4.
			40	0	3	7				2	_		160	_	16×16			8	8 ch ADC12	_	100LQFP	4.
MSP430F448 MSP430F449	48	2048	48	2	3	- 1	•		_	_			100		16×16	_	_	·	OUITIDOIL		TOOLQTT	т.

*Represents number of capture/compare registers per timer.

MSP430I	77.7	· OCI	163	_			O IVIII	***		יטט עט												
				-	imers						USC Ch A:	1						CPU				1 k
art Number 461 x	Flash (KB)	SRAM (B)	I/O (max)	Total	A.	B*	Watchdog and RTC	BOR	svs	USART (UART/SPI)	UART/LIN/ IrDA/SPI	Ch B: I ² C/SPI	LCD Segments	DMA	MPY	Comp_/	Temp A Sensor	Speed (MIPS)	ADC Ch/Res	Additional Features	Package(s)	Pric (U.S.
ISP430FG4616	92	4096	80	2	3	7	•	•	•	1	1	1	160	•	16×16	•	•	8	12 ch ADC12	(2) DAC12, +RTC (3) OPAMP	100LQFP; 113BGA	7.4
MSP430FG4617	92	8192	80	2	3	7	•	•	•	1	1	1	160	•	16×16	•	•	8	12 ch ADC12	(2) DAC12, +RTC (3) OPAMP	100LQFP; 113BGA	7.9
ISP430FG4618	116	8192	80	2	3	7	•	•	•	1	1	1	160	•	16×16	•	•	8	12 ch ADC12	(2) DAC12, +RTC (3) OPAMP	100LQFP; 113BGA	8.3
ISP430FG4619	120	4096	80	2	3	7	•	•	•	1	1	1	160	•	16×16	•	•	8	12 ch ADC12	(2) DAC12, +RTC (3) OPAMP	100LQFP; 113BGA	7.9
-461x																						
MSP430F46161	92	4096	80	2	3	7	•	•	•	1	1	1	160	•	16×16	•	_	8	_	_	100LQFP	5.4
MSP430F46171	92	8192	80	2	3	7	•	•	•	1	1	1	160	•	16×16	•	_	8	_	_	100LQFP	5.8
MSP430F46181	116	8192	80	2	3	7	•	•	•	1	1	1	160	•	16×16	•	_	8	_	_	100LQFP	6.2
MSP430F46191	120	4096	80	2	3	7	•	•	•	1	1	1	160	•	16×16	•	_	8	_	_	100LQFP	5.8
MSP430F4616	92	4096	80	2	3	7	•	•	•	1	1	1	160	•	16×16	•	•	8	12 ch ADC12	_	100LQFP	6.3
MSP430F4617	92	8192	80	2	3	7	•	•	•	1	1	1	160	•	16×16	•	•	8	12 ch ADC12	_	100LQFP	6.7
MSP430F4618	116	8192	80	2	3	7	•	•	•	1	1	1	160	•	16×16	•	•	8	12 ch ADC12	_	100LQFP	7.1
ISP430F4619	120	4096	80	2	3	7	•	•	•	1	1	1	160	•	16×16	•	•	8	12 ch ADC12	_	100LQFP	6.7
47xx																						
MSP430F4783	48	2048	72	2	3	3	•	•	•	_	2	2	160	_	32×32 [‡]	•	•	16	(3) SD16_A	_	100LQFP	4.0
MSP430F4793	60	2560	72	2	3	3	•	•	•	_	2	2	160	_	32×32 [‡]	•	•	16	(3) SD16_A	_	100LQFP	4.3
MSP430F4784	48	2048	72	2	3	3	•	•	•	-	2	2	160	_	32×32 [‡]	•	•	16	(4) SD16_A	-	100LQFP	4.0
/ISP430F4794	60	2560	72	2	3	3	•	•	•	_	2	2	160	_	32×32 [‡]	•	•	16	(4) SD16_A	_	100LQFP	4.3
471xx																						
MSP430F47163		4096	68	2	3	3	•	•	•	_	2	2	160	•	32×32 [‡]		•	16	(3) SD16_A	RTC_C	100LQFP	5.0
MSP430F47173		8192	68	2	3	3	•	•	•	_	2	2	160	•	32×32 [‡]		•	16	(3) SD16_A	RTC_C	100LQFP	5.1
MSP430F47183		8192	68	2	3	3	•	•	•	_	2	2	160	•	32×32 [‡]	•	•	16	(3) SD16_A	RTC_C	100LQFP	5.3
MSP430F47193		4096	68	2	3	3	•	•	•	_	2	2	160	•	32×32 [‡]	•	•	16	(3) SD16_A	RTC_C	100LQFP	5.5
MSP430F47126		4096	68	2	3	3	•	•	•	_	2	2	160	•	32×32 [‡]	•	•	16	(6) SD16_A	RTC_C	100LQFP	5.1
MSP430F47166		4096	68	2	3	3	•	•	•	_	2	2	160	•	32×32 [‡]	•	•	16	(6) SD16_A	RTC_C	100LQFP	5.7
MSP430F47176		8192	68	2	3	3	•	•	•	_	2	2	160	•	32×32 [‡]		•	16	(6) SD16_A	RTC_C	100LQFP	5.9
MSP430F47186		8192	68	2	3	3	•	•	•	_	2	2	160	•	32×32 [‡]		•	16	(6) SD16_A	RTC_C	100LQFP	7.4
MSP430F47196		4096	68	2	3	3		•	•	_	2	2	160	•	32×32‡			16	(6) SD16_A	RTC_C	100LQFP	7.7
MSP430F47127		4096	68	2	3	3			•	_	2	2	160		32×32‡			16	(7) SD16_A	RTC_C	100LQFP	5.2
MSP430F47167		4096	68	2	3	3				_	2	2	160		32×32 [‡]			16	(7) SD16_A	RTC_C	100LQFP	4.7
MSP430F47177 MSP430F47187		8192 8192	68 68	2	3	3				_	2	2	160 160		32×32 [‡]			16 16	(7) SD16_A	RTC_C	100LQFP	4.8
MSP430F47187 MSP430F47197		4096	68	2	3	3				_	2	2	160		32×32 [‡]			16	(7) SD16_A (7) SD16_A	RTC_C	100LQFP	6.1
G47x	120	4030	00		J	J		•	•	_	2	2	100		32×32*		•	10	(1) SD 10_A	RTC_C	100LQFP	0.3
																				DAC10	80LQFP;	
MSP430FG477	32	2048	48	2	3	3	•	•	•	_	1	1	128	-	-	•	•	8	(5) SD16_A	DAC12, (2) OPAMP DAC12,	113BGA 80LQFP;	4.7
MSP430FG478 MSP430FG479	48	2048	48	2	3	3	•		•	_	1	1	128 128	_	_			8	(5) SD16_A (5) SD16_A	(2) OPAMP DAC12,	113BGA 80LQFP;	5.5 6.2
																			.,5.	(2) OPAMP	113BGA	
47x	20	0040	40	0	0	0							100					0	(E) CD40 4	DAGGO	001.000.440004	4.7
MSP430F477	32	2048	48	2	3	3		•	•	_	1	1	128	_	_			8	(5) SD16_A	DAC12	80LQFP; 113BGA	
/ISP430F478	48	2048	48	2	3	3	•			_	1	1	128		_			8	(5) SD16_A	DAC12	80LQFP; 113BGA	5.0

Device Catalog

MSP430	DXX (JEI IE	5 -	υþ			IZ												
Part Number	Program (KB)	SRAM (KB)	I/0 (max)	Tota	Timer A*	s B*	Watchdog and RTC	PMM: BOR, SVS, SVM, LDO	USCI Ch A: UART/ Lin/irda/spi	Ch B: I ² C/SPI	DMA	MPY	Comp B	Temp Sensor	ADC Ch/Res	DAC	Additional Features	Package(s)	F (L
F51xx																			
MSP430F5131	8	1	29 27	3	3	3, 3	•	•	1	1	3 ch	32×32‡	16 ch	_	_	_	HiRes PWM, 5V I/Os	40QFN, 38TSSOP, 40DSBGA	
MSP430F5132	8	1	29 27	3	3	3, 3	•	•	1	1	3 ch	32×32 [‡]	16 ch	•	8 ch ADC10_A	_	HiRes PWM, 5V I/Os	40QFN, 38TSSOP, 40DSBGA	
MSP430F5151	16	2	29 27	3	3	3, 3	•	•	1	1	3 ch	32×32 [‡]	16 ch	_	_	_	HiRes PWM, 5V I/Os	40QFN, 38TSSOP, 40DSBGA	
MSP430F5152	16	2	29 27	3	3	3, 3	•	•	1	1	3 ch	32×32 [‡]	16 ch	•	8 ch ADC10 A	_	HiRes PWM,	40QFN, 38TSSOP,	
MSP430F5171	32	2	29	3	3	3, 3	•		1	1	3 ch	32×32‡	16 ch	_	_	_	5V I/Os HiRes PWM,	40DSBGA 40QFN, 38TSSOP,	
			27 29							·					0 ab ADC10 A		5V I/Os HiRes PWM,	40DSBGA 40QFN, 38TSSOP,	
MSP430F5172	32	2	29 27	3	3	3, 3	•	•	1	1	3 CII	32×32 [‡]	16 CII	•	8 ch ADC10_A	_	5V I/Os	40DSBGA	L
F52xx	0.1		07		F 0 0	_					0 1	00 004					4.01110	40051	
MSP430F5212	64	8	37	4	5, 3, 3		•	•	2	2	3 ch	32×32‡	•	_	_	_	1.8V I/O	48QFN	
MSP430F5213	96	8	37	4	5, 3, 3	7	•	•	2	2	3 ch	32×32 [‡]		_	_	_	1.8V I/O	48QFN	
MSP430F5214	128	8	37	4	5, 3, 3	7	•	•	2	2	3 ch	32×32 [‡]	•	_	_	_	1.8V I/O	48QFN	
MSP430F5217	64	8	53	4	5, 3, 3	7	•	•	2	2	3 ch	32×32 [‡]	•	-	_	-	1.8V I/O	64DSBGA, 64QFN, 80BGA	
MSP430F5219	128	8	53	4	5, 3, 3	7	•	•	2	2	3 ch	32×32 [‡]	•	_	_	_	1.8V I/O	64DSBGA, 64QFN, 80BGA	
MSP430F5222	64	8	37	4	5, 3, 3	7	•	•	2	2	3 ch	32×32 [‡]	•	•	8 ch ADC10	_	1.8V I/O	48QFN	
MSP430F5223	96	8	37	4	5, 3, 3	7	•	•	2	2	3 ch	32×32 [‡]	•	•	10 ch ADC10	_	1.8V I/O	48QFN	
MSP430F5224	128	8	37	4	5, 3, 3				2	2	3 ch	32×32‡			8 ch ADC10	_	1.8V I/O	48QFN	
MSP430F5227	64	8	53	4	5, 3, 3		•	•	2	2	3 ch	32×32 [‡]	•	•	10 ch ADC10	_	1.8V I/O	64DSBGA, 64QFN, 80BGA	
MSP430F5229	128	8	53	4	5, 3, 3	7			2	2	3 ch	32×32 [‡]	•	•	10 ch ADC10	_	1.8V I/O	64DSBGA, 64QFN,	
				·											10 011710010		1.00 1/0	80BGA	
MSP430F5232	64	8	37	4	5, 3, 3	7	•	•	2	2	3	32×32 [‡]	•	•	_	_	_	48VQFN	
MSP430F5234	128	8	37	4	5, 3, 3	7	•	•	2	2	3	32×32 [‡]		•	_	_	_	48VQFN	
MSP430F5237	64	8	53	4	5, 3, 3	7	•	•	2	2	3	32×32 [‡]	•	•	_	_	_	64VQFN, 80BGA	
MSP430F5239	128	8	53	4	5, 3, 3	7	•	•	2	2	3	32×32 [‡]	•	•	_	_	_	64VQFN, 80BGA	
MSP430F5242	64	8	37	4	5, 3, 3	7	•	•	2	2	3	32×32 [‡]	•	•	10-bit SAR	_	_	48VQFN	
MSP430F5244	128	8	37	4	5, 3, 3	7	•	•	2	2	3	$32 \times 32^{\ddagger}$	•	•	10-bit SAR	_	_	48VQFN	
MSP430F5247	64	8	53	4	5, 3, 3	7	•	•	2	2	3	32×32 [‡]	•	•	10-bit SAR	_	_	64VQFN, 80BGA	
MSP430F5249	128	8	53	4	5, 3, 3	7	•	•	2	2	3	32×32 [‡]	•	•	10-bit SAR	_	_	64VQFN, 80BGA	
MSP430F5252	128	16	53	4	5, 3, 3	7	•	•	4	4	3	32×32‡	•	•	_	_	1.8V I/O	64VQFN, 80BGA	
MSP430F5253	128	16	53	4	5, 3, 3	7			4	4	3	32×32 [‡]			10-bit SAR	_	1.8V I/O	64VQFN, 80BGA	
MSP430F5254	128	32	53	4	5, 3, 3				4	4	3	32×32 [‡]			- TO DICO/III		1.8V I/O	64VQFN, 80BGA	
MSP430F5255	128	32	53	4	5, 3, 3				4	4	3	32×32 [‡]			10-bit SAR		1.8V I/O	64VQFN, 80BGA	
									·		-				TO-DIT SAIT			,	
MSP430F5256	128	16	53	4	5, 3, 3		•	•	4	4	3	32×32 [‡]		•		_	1.8V I/O	64VQFN, 80BGA	
MSP430F5257	128	16	53	4	5, 3, 3		•	•	4	4	3	32×32 [‡]		•	10-bit SAR	_	1.8V I/O	64VQFN, 80BGA	
MSP430F5258	128	32	53	4	5, 3, 3		•	•	4	4	3	32×32‡		•	_	_	1.8V I/O	64VQFN, 80BGA	
MSP430F5259 F53x	128	32	53	4	5, 3, 3	7	•	•	4	4	3	32×32 [‡]	•	•	10-bit SAR	_	1.8V I/O	64VQFN, 80BGA	u
MSP430F5304	8	6	31	4	5, 3, 3	7	•	•	1	1	3 ch	32×32‡	_	•	8 ch (6/2) ADC10	_	_	48QFN, 48LQFP	Т
MSP430F5308	16	6	47	4	5, 3, 3		•		2	2		32×32 [‡]		•	12 ch (10/2)	_	_	48QFN, 48LQFP,	
MSP430F5309															ADC10 12 ch (10/2)			64QFN, 80BGA 48QFN, 48LQFP,	
	24	6	47	4	5, 3, 3		•	•	2	2		32×32 [‡]		•	ADC10 12 ch (10/2)		_	64QFN, 80BGA 48QFN, 48LQFP,	
MSP430F5310	32	6	47	4	5, 3, 3		•	•	2	2		32×32 [‡]		•	ADC10	_	_	64QFN, 80BGA	
MSP430F5324	64	6	48	4	5, 3, 3		•		2	2		32×32‡		•	16 ch ADC12 A	_	_	64QFN, 80BGA	
MSP430F5325 MSP430F5326	64	6 8	63	4	5, 3, 3		•	•	2 2	2	3 ch	32×32 [‡]		•	16 ch ADC12 A 16 ch ADC12 A	_	_	80LQFP	
MSP430F5326 MSP430F5327	96 96	8	48 63	4	5, 3, 3 5, 3, 3		•	•	2	2	3 ch	32×32 [‡]		•	16 ch ADC12 A	_	_	64QFN, 80BGA 80LQFP	
MSP430F5328	128	10	48	4	5, 3, 3				2	2	3 ch	32×32 [‡]			16 ch ADC12 A	_	_	64QFN, 80BGA	
MSP430F5329	128	10	63	4	5, 3, 3				2	2		32×32 [‡]			16 ch ADC12 A	_	_	80LQFP	
	128	10	74		5, 3, 3				2	2			_	_					400

¹Prices are quoted in U.S. dollars and represent year 2014 suggested resale price. [†]Additional 2K of SRAM available if USB is disabled.

‡Supports 64 bit result length.

*Represents number of capture/compare registers per timer. New products are listed in **bold red**.

					Timers			Tinued PMM: BOR.	USCI										1 kı
art Number 3x (continued)	Program (KB)	SRAM (KB)	I/O (max)	Total	A*	В*	Watchdog and RTC	SVS, SVM, LDO	Ch A: UART/ Lin/Irda/SPI	Ch B: I ² C/SPI	DMA	MPY	Comp B	Temp Sensor	ADC Ch/Res	DAC	Additional Features	Package(s)	Pric (U.S.
SP430F5335	256	18	74	4	5, 3, 3	7	•	•	2	2	6 ch	32×32 [‡]	•	•	16 ch ADC12 A	_	Battery backup	100LQFP, 113BGA	3.3
SP430F5336	128	18	74	4	5, 3, 3	7	•	•	2	2	6 ch	32×32 [‡]	•	•	16 ch ADC12 A	•	Battery backup	100LQFP, 113BGA	3.4
SP430F5338	256	18	74	4	5, 3, 3	7	•	•	2	2	6 ch	32×32 [‡]	•	•	16 ch ADC12 A		Battery backup	100LQFP, 113BGA	
SP430F5340	64	6	38	4	5, 3, 3	7	•	•	2	2	3 ch	32×32 [‡]	•	•	9 ch ADC12 A	_	_	48QFN 48QFN	2.1
SP430F5341 SP430F5342	96 128	8	38 38	4	5, 3, 3 5, 3, 3	7	•		2	2	3 ch 3 ch	32×32 [‡] 32×32 [‡]	•	•	9 ch ADC12 A 9 ch ADC12 A	_	_	48QFN	2.4
SP430F5358	384	$32 + 2^{\dagger}$	74		5, 3, 3	7			3	3	6 ch	32×32 [‡]			16 ch ADC12	•	_	100LQFP, 113BGA	6.0
SP430F5359	512	64 + 2†	74	4	5, 3, 3	7	•	•	3	3	6 ch	32×32 [‡]	•	•	16 ch ADC12	•	_	100LQFP, 113BGA	6.0
4x SP430F5418A	128	16	87	3	5, 3	7		•	2	2	3 ch	32×32‡	_		16 ch ADC12 A			80LQFP	2.6
SP430F5419A	128	16	87	3	5, 3	7	•		4	4	3 ch	32×32 [‡]	_		16 ch ADC12 A	_		100LQFP, 113BGA	
SP430F5435A	192	16	87	3	5, 3	7			2	2	3 ch	32×32 [‡]			16 ch ADC12 A	_	_	80LQFP	3.8
			87			7			4	4		32×32 [‡]						100LQFP, 113BGA	
SP430F5436A	192	16		3	5, 3		•		2	2			_	•	16 ch ADC12 A	_	_		4.10
SP430F5437A	256 256	16	87 87	3	5, 3 5, 3	7 7	•	•	4	4		32×32 [‡] 32×32 [‡]	_	•	16 ch ADC12 A		_	80LQFP	4.3
SP430F5438A 5xx	200	16	0/	3	ე, ა	1	•	•	4	4	3 ch	32×32*	_	•	16 ch ADC12 A	_	_	100LQFP, 113BGA	4.5
SP430F5500	8	4 + 2 [†]	31	4	5, 3, 3	7	•	•	1	1	3 ch	32×32 [‡]	4	_	_	_	USB	48QFN	1.4
SP430F5501	16	$4 + 2^{\dagger}$	31	4	5, 3, 3	7	•	•	1	1	3 ch	32×32 [‡]	4	_	_	_	USB	48QFN	1.6
SP430F5502	24	$4 + 2^{\dagger}$	31	4	5, 3, 3	7	•	•	1	1		32×32 [‡]	4	_	_	_	USB	48QFN	1.6
SP430F5503	32	$4 + 2^{\dagger}$	31	4	5, 3, 3	7	•	•	1	1	3 ch	32×32 [‡]	4	_	_	_	USB	48QFN	1.7
SP430F5504	8	4 + 2 [†]	31	4	5, 3, 3	7	•	•	1	1		32×32 [‡]	_	•	8 ch (6/2) ADC10	_	USB	48QFN, 48LQFP	1.7
SP430F5505	16	$4 + 2^{\dagger}$	31	4	5, 3, 3	7	•		1	1	3 ch	32×32 [‡]	_		8 ch (6/2) ADC10	_	USB	48QFN	1.7
SP430F5506	24	$4 + 2^{\dagger}$	31	4	5, 3, 3	7	•	•	1	1	3 ch	32×32‡	_	•	8 ch (6/2) ADC10	_	USB	48QFN	1.8
SP430F5507	32	$4 + 2^{\dagger}$	31	4	5, 3, 3	7	•	•	1	1		32×32 [‡]	_	•	8 ch (6/2) ADC10	_	USB	48QFN	1.9
SP430F5508	16	4 + 2 [†]	47	4	5, 3, 3	7	•	•	2	2	3 ch	32×32 [‡]	8	•	12 ch (10/2) ADC10	_	USB	48QFN, 48LQFP, 64QFN, 80BGA	1.8
SP430F5509	24	4 + 2 [†]	47	4	5, 3, 3	7	•	•	2	2	3 ch	32×32 [‡]	8	•	12 ch (10/2) ADC10	_	USB	48QFN, 48LQFP, 64QFN, 80BGA	1.8
SP430F5510	32	4 + 2 [†]	47	4	5, 3, 3	7	•	•	2	2	3 ch	32×32 [‡]	8	•	12 ch (10/2) ADC10	_	USB	48QFN, 48LQFP, 64QFN, 80BGA	1.9
SP430F5513	32	$4 + 2^{\dagger}$	47	4	5, 3, 3	7	•	•	2	2	3 ch	32×32 [‡]		_	_	_	USB	64QFN, 80BGA	3.2
SP430F5514	64	4 + 2 [†]	47	4	5, 3, 3	7		•	2	2	3 ch	32×32 [‡]		_	_	_	USB	64QFN, 80BGA	3.5
SP430F5515	64	4 + 2 [†]	63	4	5, 3, 3	7			2	2	3 ch	32×32 [‡]		_	_	_	USB	80LQFP	3.3
SP430F5517	96	6 + 2 [†]	63	4	5, 3, 3	7			2	2		32×32 [‡]		_	_	_	USB	80LQFP	3.7
SP430F5519	128	$8 + 2^{\dagger}$	63	4	5, 3, 3	7			2	2	3 ch	32×32 [‡]		_	_	_	USB	80LQFP	3.9
SP430F5521	32	6 + 2 [†]	63	4	5, 3, 3	7			2	2	3 ch	32×32 [‡]		•	16 ch ADC12 A	_	USB	80LQFP	3.3
SP430F5522	32	8 + 2 [†]	47	4	5, 3, 3	7			2	2	3 ch	32×32 [‡]			12 ch ADC12 A	_	USB	64QFN, 80BGA	3.4
SP430F5524	64	4 + 2 [†]	47	4	5, 3, 3	7			2	2	3 ch	32×32 [‡]		•	12 ch ADC12 A		USB	64QFN, 80BGA	3.5
SP430F5525	64	$4 + 2^{\dagger}$ $4 + 2^{\dagger}$	63	4	5, 3, 3	7			2	2		32×32 [‡]			16 ch ADC12 A	_	USB	80LQFP	3.7
			47	4		7	_		2	2						_			
SP430F5526 SP430F5527	96 96	$6 + 2^{\dagger}$ $6 + 2^{\dagger}$	63	4	5, 3, 3 5, 3, 3	7	•	•	2	2		32×32 [‡] 32×32 [‡]		•	12 ch ADC12 A 16 ch ADC12 A		USB	64QFN, 80BGA 80LQFP	3.8
								_	2							_			
SP430F5528	128	8 + 2 [†]		4	5, 3, 3	7	•	•	2	2		32×32 [‡]		•	16 ch ADC12 A	_	USB	64QFN, 80BGA	3.9
SP430F5529 63x	128	8 + 2 [†]	63	4	5, 3, 3	7	•	•	2	2	3 CII	32×32 [‡]		•	16 ch ADC12 A	_	USB	80 LQFP	4.0
SP430F5630	128	16 + 2 [†]	74	4	5, 3, 3	7	•	•	2	2	6 ch	32×32 [‡]	•	_	_	_	USB, Backup battery switch	100LQFP, 113BGA	3.6
SP430F5631	192	16 + 2 [†]	74	4	5, 3, 3	7	•	•	2	2	6 ch	32×32 [‡]	•	_	_	_	USB, Backup battery switch	100LQFP, 113BGA	4.1
SP430F5632	256	16 + 2 [†]	74	4	5, 3, 3	7	•	•	2	2	6 ch	32×32‡	•	_	_	_	USB, Backup battery switch	100LQFP, 113BGA	4.5
SP430F5633	128	16 + 2 [†]	74	4	5, 3, 3	7	•	•	2	2	6 ch	32×32 [‡]	•	•	16 ch ADC12 A	-	USB, Backup battery switch	100LQFP, 113BGA	4.2
SP430F5634	192	16 + 2 [†]	74	4	5, 3, 3	7	•	•	2	2	6 ch	32×32 [‡]	•	•	16 ch ADC12 A	-	USB, Backup battery switch	100LQFP, 113BGA	4.4
SP430F5635	256	16 + 2 [†]	74	4	5, 3, 3	7	•	•	2	2	6 ch	32×32 [‡]	•	•	16 ch ADC12 A	-	USB, Backup battery switch	100LQFP, 113BGA	4.7
SP430F5636	128	16 + 2 [†]	74	4	5, 3, 3	7	•	•	2	2	6 ch	32×32 [‡]	•	•	16 ch ADC12 A	•	USB, Backup battery switch	100LQFP, 113BGA	4.8
SP430F5637	192	16 + 2 [†]	74	4	5, 3, 3	7	•	•	2	2	6 ch	32×32 [‡]	•	•	16 ch ADC12 A	•	USB, Backup battery switch	100LQFP, 113BGA	5.1
SP430F5638	256	16 + 2 [†]	74	4	5, 3, 3	7	•	•	2	2	6 ch	32×32 [‡]	•	•	16 ch ADC12 A	•	USB, Backup battery switch	100LQFP, 113BGA	5.3
65x SP430F5658	384	32 + 2*	74	4	5, 3, 3	7	•	•	3	3	6 ch	32×32 [‡]	•	•	16 ch ADC12	•	USB	100LQFP, 113BGA	6.0
SP430F5659	512	32 + 2 64 + 2*			5, 3, 3	7			3	3		32×32 [‡]			16 ch ADC12		USB	100LQFP, 113BGA	6.0
מנוטנו וווטד וע	JIZ	UT T Z	14	4	0, 0, 0	1	_	_	J	J	U UII	OFYOR,	_	_	10 011 AD 012	-	UUD	TOULUIT, ITODUA	0.0

				16-	Bit Tim	ers		PMM:	USCI										1
Part Number	Flash (KB)	SRAM (KB)	I/O (max)	Total	A*	B.	Watchdog and RTC	BOR, SVS, SVM, LDO	Ch A: UART/ Lin/irda/spi	Ch B: I ² C/SPI	DMA	MPY	Comp B	Temp Sensor	ADC Ch/Res	DAC	Additional Features	Packages	Pr (U.
F663x	100	10 . Ot	74	_	F 0 0	7			0	0	Cab	2020t					LICD I CD	100L0ED 110D0A	
ISP430F6630	128	16 + 2 [†]	74	4	5, 3, 3		•	•	2	2	6 ch	32×32 [‡]	•	_		_	USB, LCD	100LQFP, 113BGA	4
ISP430F6631 ISP430F6632	192 256	$16 + 2^{\dagger}$ $16 + 2^{\dagger}$	74 74	4	5, 3, 3		•	•	2	2	6 ch	32×32 [‡] 32×32 [‡]	•	_	_	_	USB, LCD USB, LCD	100LQFP, 113BGA 100LQFP, 113BGA	4
ISP430F6633	128	$16 + 2^{\dagger}$ $16 + 2^{\dagger}$	74	4	5, 3, 3 5, 3, 3		•	•	2	2	6 ch	32×32 [‡]		_	16 ch ADC12 A		USB, LCD	100LQFP, 113BGA	5
ISP430F6634	192	16 + 2 [†]	74	4	5, 3, 3		•		2	2	6 ch	32×32 [‡]			16 ch ADC12 A	_	USB, LCD	100LQFP, 113BGA	
ISP430F6635	256	16 + 2 [†]	74	4	5, 3, 3				2	2	6 ch	32×32 [‡]			16 ch ADC12 A		USB, LCD	100LQFP, 113BGA	5
ISP430F6636	128	16 + 2 [†]	74	4	5, 3, 3		•		2	2	6 ch	32×32 [‡]			16 ch ADC12 A	•	USB, LCD	100LQFP, 113BGA	4
ISP430F6637	192	16 + 2 [†]	74	4	5, 3, 3				2	2	6 ch	32×32 [‡]			16 ch ADC12 A		USB, LCD	100LQFP, 113BGA	5
ISP430F6638	256	16 + 2 [†]	74	4	5, 3, 3				2	2	6 ch	32×32 [‡]			16 ch ADC12 A		USB, LCD	100LQFP, 113BGA	5
F643x	230	10 + 2	74	4	0, 0, 0	, ,	•	•	2		0 GH	32×32	•	_	10 CITADOTZ A	_	USB, LGD	TOULUFF, TTOBUA	
	100	10	74	4	F 0 0	7			0	0	Cab	2020±			10 ah AD010 A		LCD	1001 000 110004	
ISP430F6433	128	18	74	4	5, 3, 3		•	•	2	2	6 ch	32×32 [‡]	•	•	16 ch ADC12 A	_	LCD	100LQFP, 113BGA	3
ISP430F6435	256	18	74	4	5, 3, 3		•	•	2	2	6 ch	32×32 [‡]	•		16 ch ADC12 A	_	LCD	100LQFP, 113BGA	4
ISP430F6436	128	18	74	4	5, 3, 3		•	•	2	2	6 ch	32×32 [‡]	•	•	16 ch ADC12 A	•	LCD	100LQFP, 113BGA	4
ISP430F6438	256	18	74	4	5, 3, 3	7	•	•	2	2	6 ch	32×32 [‡]	•	•	16 ch ADC12 A	•	LCD	100LQFP, 113BGA	4
F645x																			
ISP430F6458	384	34	74	4	5, 3, 3		•	•	3	3	6 ch	32×32 [‡]	•	•	16 ch ADC12	•	LCD	100LQFP, 113BGA	7
ISP430F6459	512	66	74	4	5, 3, 3	7	•	•	3	3	6 ch	32×32 [‡]	•	•	16 ch ADC12	•	LCD	100LQFP, 113BGA	7
-665x																			
ISP430F6658	384	$32 + 2^{\dagger}$	74	4	5, 3, 3	7	•	•	3	3	6 ch	32×32 [‡]	•	•	16 ch ADC12	•	USB, LCD	100LQFP, 113BGA	7
ISP430F6659	512	$64 + 2^{\dagger}$	74	4	5, 3, 3	7	•	•	3	3	6 ch	$32 \times 32^{\ddagger}$	•	•	16 ch ADC12	•	USB, LCD	100LQFP, 113BGA	7
67xx																			
ISP430F6720	16	1	72	4	5, 3, 3	7	•	•	3	1	6 ch	32×32 [‡]	_	•	8 ch ADC10	_	LCD	100LQFP, 80LQFP	2
ISP430F6721	32	2	72	4	5, 3, 3		•	•	3	1	6 ch	32×32 [‡]	_	•	8 ch ADC10	_	LCD	100LQFP, 80LQFP	2
ISP430F6723	64	4	72	4	5, 3, 3	7	•	•	3	1	6 ch	32×32 [‡]	_	•	8 ch ADC10	_	LCD	100LQFP, 80LQFP	2
ISP430F6724	96	4	72	4	5, 3, 3	7	•	•	3	1	6 ch	32x32 [‡]	_	•	8 ch ADC10	_	LCD	100LQFP, 80LQFP	2
ISP430F6725	128	4	72	4	5, 3, 3		•	•	3	1	6 ch	32×32‡	_	•	8 ch ADC10	_	LCD	100LQFP, 80LQFP	2
ISP430F6726	128	8	72	4	5, 3, 3		•	•	3	1	6 ch	32×32 [‡]	_	•	8 ch ADC10	_	LCD	100LQFP, 80LQFP	2
ISP430F6730	16	1	72	4	5, 3, 3		•	•	3	1	6 ch	32×32‡	_	•	8 ch ADC10	_	LCD	100LQFP, 80LQFP	2
ISP430F6731	32	2	72	4	5, 3, 3		•	•	3	1	6 ch	32×32 [‡]	_	•	8 ch ADC10	_	LCD	100LQFP, 80LQFP	2
ISP430F6733	64	4	72	4	5, 3, 3		•	•	3	1	6 ch	32×32 [‡]	_	•	8 ch ADC10	_	LCD	100LQFP, 80LQFP	2
ISP430F6734	96	4	72	4	5, 3, 3		•		3	1	6 ch	32×32 [‡]	_		8 ch ADC10	_	LCD	100LQFP, 80LQFP	3
ISP430F6735	128	4	72	4	5, 3, 3		•	•	3	1	6 ch	32×32 [‡]	_		8 ch ADC10	_	LCD	100LQFP, 80LQFP	3
ISP430F6736	128	8			5, 3, 3				3	1		32×32 [‡]			8 ch ADC10		LCD		
13543050730	120	0	72	4	0, 0, 0) /	•	•	J	'	6 ch	32×32	_		8 ch ADC10/		LUD	100LQFP, 80LQFP	3
ISP430F6745	128	32	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	4 ch SD24	_	LCD, AES	100LQFP, 128LQFP	4
ISP430F67451	128	16	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 4 ch SD24	_	LCD	100LQFP, 128LQFP	3
ISP430F6746	256	16	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 4 ch SD24	_	LCD, AES	100LQFP, 128LQFP	- 4
ISP430F67461	256	16	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 4 ch SD24	_	LCD	100LQFP, 128LQFP	
ISP430F6747	256	32	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 4 ch SD24	_	LCD, AES	100LQFP, 128LQFP	
ISP430F67471	256	32	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 4 ch SD24	_	LCD	100LQFP, 128LQFP	
ISP430F6748	512	16	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 4 ch SD24	-	LCD, AES	100LQFP, 128LQFP	6
ISP430F67481	512	16	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 4 ch SD24	-	LCD	100LQFP, 128LQFP	
ISP430F6749	512	32	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 4 ch SD24	-	LCD, AES	100LQFP, 128LQFP	(
															8 ch ADC10/				

¹Prices are quoted in U.S. dollars and represent year 2014 suggested resale price. *Represents number of capture/compare registers per timer. †Additional 2K of SRAM available if USB is disabled. †Supports 64-bit result length. New products are listed in **bold red**.

MSP430I				_	D'4 T'				Hook										
art Number	Flash (KB)	SRAM (KB)	I/O (max)	16- Total	Bit Time A*	ers B*	Watchdog and RTC	PMM: BOR, SVS, SVM, LDO	Ch A: UART/ LIN/IrDA/SPI	Ch B: I ² C/SPI	DMA	MPY	Comp B	Temp Sensor	ADC Ch/Res	DAC	Additional Features	Packages	1 Pri (U.S
67xx (continu	ed)														0 ab ADC10/				
SP430F6765	128	16	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 6 ch SD24	-	LCD, AES	100LQFP, 128LQFP	4.
SP430F67651	128	16	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32‡	•	•	8 ch ADC10/ 6 ch SD24	_	LCD	100LQFP, 128LQFP	4.
SP430F6766	256	16	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 6 ch SD24	_	LCD, AES	100LQFP, 128LQFP	5.
SP430F67661	256	16	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 6 ch SD24	_	LCD	100LQFP, 128LQFP	4.
SP430F6767	256	32	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 6 ch SD24	_	LCD, AES	100LQFP, 128LQFP	5
SP430F67671	256	32	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 6 ch SD24	_	LCD	100LQFP, 128LQFP	5
SP430F6768	512	16	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32‡	•	•	8 ch ADC10/ 6 ch SD24	_	LCD, AES	100LQFP, 128LQFP	6
SP430F67681	512	16	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 6 ch SD24	_	LCD	100LQFP, 128LQFP	6
SP430F6769	512	32	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 6 ch SD24	_	LCD, AES	100LQFP, 128LQFP	6
SP430F67691	512	32	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 6 ch SD24	_	LCD	100LQFP, 128LQFP	6
SP430F6775	128	16	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 7 ch SD24	_	LCD, AES	100LQFP, 128LQFP	4
P430F67751	128	16	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 7 ch SD24	_	LCD	100LQFP, 128LQFP	2
P430F6776	256	16	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32‡	•	•	8 ch ADC10/ 7 ch SD24	_	LCD, AES	100LQFP, 128LQFP	Ę
SP430F67761	256	16	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32‡	•	•	8 ch ADC10/ 7 ch SD24	_	LCD	100LQFP, 128LQFP	į
6P430F6777	256	32	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32‡	•	•	8 ch ADC10/ 7 ch SD24	_	LCD, AES	100LQFP, 128LQFP	5
SP430F67771	256	32	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32‡	•	•	8 ch ADC10/ 7 ch SD24	_	LCD	100LQFP, 128LQFP	Ę
P430F6778	512	16	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 7 ch SD24	_	LCD, AES	100LQFP, 128LQFP	6
P430F67781	512	16	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 7 ch SD24	_	LCD	100LQFP, 128LQFP	(
SP430F6779	512	32	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 7 ch SD24	_	LCD, AES	100LQFP, 128LQFP	6
P430F67791	512	32	90	4	5, 3, 3	7	•	•	4	2	6 ch	32×32 [‡]	•	•	8 ch ADC10/ 7 ch SD24	_	LCD	128LQFP, 100LQFP	6
SP430F6779A	512	32	90	4	5, 3, 3	7	•	•	4	2	3	32×32 [‡]	•	•	8 ch ADC10/ 7 ch SD24	_	LCD, AES	100LQFP, 128LQFP	6
SP430F6778A	512	16	90	4	5, 3, 3	7	•	•	4	2	3	32×32 [‡]	•	•	8 ch ADC10/ 7 ch SD24	_	LCD, AES	100LQFP, 128LQFP	6
P430F6777A	256	32	90	4	5, 3, 3	7	•	•	4	2	3	32×32 [‡]	•	•	8 ch ADC10/ 7 ch SD24	_	LCD, AES	100LQFP, 128LQFP	
SP430F6776A	256	16	90	4	5, 3, 3	7	•	•	4	2	3	32×32 [‡]	•	•	8 ch ADC10/ 7 ch SD24	_	LCD, AES	100LQFP, 128LQFP	Ę
P430F6775A	128	16	90	4	5, 3, 3	7	•	•	4	2	3	32×32‡	•	•	8 ch ADC10/ 7 ch SD24	_	LCD, AES	100LQFP, 128LQFP	4
P430F6769A	512	32	90	4	5, 3, 3	7	•	•	4	2	3	32×32‡	•	•	8 ch ADC10/ 6 ch SD24	_	LCD, AES	100LQFP, 128LQFP	6
P430F6768A	512	16	90	4	5, 3, 3	7	•	•	4	2	3	32×32‡	•	•	8 ch ADC10/ 6 ch SD24	_	LCD, AES	100LQFP, 128LQFP	6
P430F6767A	256	32	90	4	5, 3, 3	7	•	•	4	2	3	32×32 [‡]	•	•	8 ch ADC10/ 6 ch SD24	_	LCD, AES	100LQFP, 128LQFP	Ę
P430F6766A	256	16	90	4	5, 3, 3	7	•	•	4	2	3	32×32 [‡]	•	•	8 ch ADC10/ 6 ch SD24	_	LCD, AES	100LQFP, 128LQFP	Ę
SP430F6765A	128	16	90	4	5, 3, 3		•		4	2	3	32×32 [‡]			8 ch ADC10/		LCD, AES	100LQFP, 128LQFP	4

¹Prices are quoted in U.S. dollars and represent year 2014 suggested resale price.

*Represents number of capture/compare registers per timer.

*Additional 2K of SRAM available if USB is disabled.

*Supports 64-bit result length.

New products are listed in **bold red**.

MSP430F	6хх	Seri	es –	Up	to 2	5 N	NHz wi	th LCD	(continu	ıed)									
Part Number	Flash (KB)	SRAM (KB)	I/O (max)	16- Total	Bit Time A	ers B*	Watchdog and RTC	PMM: Bor, SVS, SVM, LDO	USCI Ch A: UART/ Lin/irda/spi	Ch B: I ² C/SPI	DMA	MPY	Comp B	Temp Sensor	ADC Ch/Res	DAC	Additional Features	Packages Packages	1 ku Price (U.S. S
MSP430F6749A	512	32	90	4	5, 3, 3	7	•	•	4	2	3	32×32‡	•	•	8 ch ADC10/ 4 ch SD24	_	LCD, AES	100LQFP, 128LQFP	6.49
MSP430F6748A	512	16	90	4	5, 3, 3	7	•	•	4	2	3	32×32‡	•	•	8 ch ADC10/ 4 ch SD24	_	LCD, AES	100LQFP, 128LQFP	6.18
MSP430F6747A	256	32	90	4	5, 3, 3	7	•	•	4	2	3	32×32‡	•	•	8 ch ADC10/ 4 ch SD24	_	LCD, AES	100LQFP, 128LQFP	4.79
MSP430F6746A	256	16	90	4	5, 3, 3	7	•	•	4	2	3	32×32‡	•	•	8 ch ADC10/ 4 ch SD24	_	LCD, AES	100LQFP, 128LQFP	4.94
MSP430F6745A	128	16	90	4	5, 3, 3	7	•	•	4	2	3	32×32‡	•	•	8 ch ADC10/ 4 ch SD24	_	LCD, AES	100LQFP, 128LQFP	4.13
/ISP430F67791A	512	32	90	4	5, 3, 3	7	•	•	4	2	3	32×32 [‡]	•	•	8 ch ADC10/ 7 ch SD24	_	LCD	100LQFP, 128LQFP	6.48
/ISP430F67781A	512	16	90	4	5, 3, 3	7	•	•	4	2	3	32×32‡	•	•	8 ch ADC10/ 7 ch SD24	_	LCD	100LQFP, 128LQFP	6.37
MSP430F67771A	256	32	90	4	5, 3, 3	7	•	•	4	2	3	32×32 [‡]	•	•	8 ch ADC10/ 7 ch SD24	_	LCD	100LQFP, 128LQFP	5.25
/ISP430F67761A	256	16	90	4	5, 3, 3	7	•	•	4	2	3	32×32 [‡]	•	•	8 ch ADC10/ 7 ch SD24	_	LCD	100LQFP, 128LQFP	5.13
MSP430F67751A	128	16	90	4	5, 3, 3	7	•	•	4	2	3	32×32 [‡]	•	•	8 ch ADC10/ 7 ch SD24	-	LCD	100LQFP, 128LQFP	4.32
MSP430F67691A	512	32	90	4	5, 3, 3	7	•	•	4	2	3	32×32 [‡]	•	•	8 ch ADC10/ 6 ch SD24	_	LCD	100LQFP, 128LQFP	6.25
/ISP430F67681A	512	16	90	4	5, 3, 3	7	•	•	4	2	3	32×32 [‡]	•	•	8 ch ADC10/ 6 ch SD24	_	LCD	100LQFP, 128LQFP	6.14
MSP430F67671A	256	32	90	4	5, 3, 3	7	•	•	4	2	3	32×32 [‡]	•	•	8 ch ADC10/ 6 ch SD24	_	LCD	100LQFP, 128LQFP	5.02
MSP430F67661A	256	16	90	4	5, 3, 3	7	•	•	4	2	3	32×32‡	•	•	8 ch ADC10/ 6 ch SD24	_	LCD	100LQFP, 128LQFP	4.90
MSP430F67651A	128	16	90	4	5, 3, 3	7	•	•	4	2	3	32×32 [‡]	•	•	8 ch ADC10/ 6 ch SD24	_	LCD	100LQFP, 128LQFP	4.09
/ISP430F67491A	512	32	90	4	5, 3, 3	7	•	•	4	2	3	32×32 [‡]	•	•	8 ch ADC10/ 4 ch SD24	-	LCD	100LQFP, 128LQFP	6.02
MSP430F67481A	512	16	90	4	5, 3, 3	7	•	•	4	2	3	32×32 [‡]	•	•	8 ch ADC10/ 4 ch SD24	-	LCD	100LQFP, 128LQFP	5.91
MSP430F67471A	256	32	90	4	5, 3, 3	7	•	•	4	2	3	32×32 [‡]	•	•	8 ch ADC10/ 4 ch SD24	-	LCD	100LQFP, 128LQFP	4.79
MSP430F67461A	256	16	90	4	5, 3, 3	7	•	•	4	2	3		•	•	8 ch ADC10/ 4 ch SD24	_	LCD	100LQFP, 128LQFP	4.67
MSP430F67451A	128	16	90	4	5, 3, 3	7	•	•	4	2	3		•	•	8 ch ADC10/ 4 ch SD24	_	LCD	100LQFP, 128LQFP	3.86
NSP430F67621	64	4	72	4	5, 3, 3	7	•	•	3	1	3	32×32 [‡]	_	•	8 ch ADC10/ 3 ch SD24	_	LCD	100LQFP, 80LQFP	2.70
MSP430F67641	128	8	72	4	5, 3, 3	7	•	•	4	1	3	32×32 [‡]	_	•	8 ch ADC10/ 3 ch SD24	_	LCD	100LQFP, 80LQFP	2.90

¹Prices are quoted in U.S. dollars and represent year 2014 suggested resale price. *Represents number of capture/compare registers per timer. †Additional 2K of SRAM available if USB is disabled. †Supports 64-bit result length. New products are listed in **bold red**.

Differentiated Performance: If you need low-voltage operation, industrial temperature range, or embedded RF, then you have come to the right place!

Application-Sp	ecific MS	P430) Devi	ces							
Application	Part Number	Flash (KB)	SRAM (KB)	16-Bi			ADC	Additional Features	Related Devices	Package(s)	1 ku Price ¹
NFC	RF430CL330H		(KD)		-	_	AD0	Dynamic NFC interface transponder, NFC tag type 4	— DEVICES	14TSSOP	0.85
Low Voltage (0.9V)	MSP430L092	_	2	2	2	_	ADC8	DAC8, COMP, SVS, temp. sensor, 11 I/Os, ROM-version available	_	14TSSOP	1.00
Contactless Power	MSP430BQ1010	_	_	_	_	_	_	Fixed-function, Qi-certified software for contactless power applications (receiver). Compliant with the Wireless Power Consortium. Comes pre-loaded by default.	BQ25046, BQ500110	32QFN	1.80
Haptics	MSP430TCH5E	_	_	_	_	_	_	Haptics-enabled device authenticated to run Immersion Touchsense technology	_	28TSSOP, 32QFN	1.80

¹Prices are quoted in U.S. dollars and represent year 2014 suggested resale price.

*Represents number of capture/compare registers per timer.

Enhanced	Perfor	man	ce														
Part Number Auto and EP	Frequency (MHz)	Flash (KB)	SRAM (B)	GPIO	16-bit Timers	Watchdog and RTC	Brown Out Reset	USI (I ² C/SPI)	DMA	MPY	Comp	Temp Sensor	ADC	Temp Range (°C)	Additional Features	Pin/Package	1 ku Price¹ (U.S. \$)
MSP430F2619S-HT	16	120	4096	48	2	•	•	2	_	_	•	•	8 ch ADC12	-55 to 150	DAC12	64LQFP	68.75/100 u
MSP430F2013-EP	16	2	128	10	1	•	•	1	—	_	•	•	4 ch SD16	-40 to 125	_	16QFN	1.75/100 u
MSP430F2274-EP	16	32	1024	32	2	•	•	2	_	_	•	•	12 ch ADC12	-55 to 125	(2) Op Amp	38TSSOP, 40QFN	6.75
MSP430F249-EP	16	60	2048	48	2	•	•	2	—	16×16	•	•	8 ch ADC12	-55 to 125	_	64LQFP	11.88/100 u
MSP430F2618-EP	16	116	8192	48	2	•	•	2	•	16×16	•	•	8 ch ADC12	-40 to 105	DAC12	113BGA	26.00/100 u
MSP430G2230-EP	16	2	128	4	1	•	•	1	—	_	_	•	4 ch SAR10	-40 to 125	_	8SOIC	0.52
MSP430G2231-EP	16	2	128	10	1	•	•	1	_	_	_	•	8 ch SAR10	-40 to 125	_	14TSSOP	1.05
MSP430G2302-EP	16	_	128	16	1	•	•	1	-	_	-	•	_	-40 to 85	_	14TSSOP	0.85

¹Prices are quoted in U.S. dollars and represent year 2014 suggested resale price.

Note: Additional 105°C devices available on page 14.

MSP430i2	Oxx I	-Seri	es –	Up to	16	MHz	Z									
					Timers			Brown								
Part Number	Flash (KB)	SRAM (B)	I/O (Max)	Total	Δ*	R*	Watchdog and RTC	Out Reset	SVS	USART (UART/SPI)	MPY	Temp Sensor	ADC Ch/Res	Temp Range (°C)	Pin/Package	1 ku Price ¹ (U.S. \$)
i20xx	(112)	(5)	(max)	Total			ana mo	110001	0.0	(371117011)		0011001	7150 011/1100	i ilango (o)	i iiii adkago	(0.01 \$)
MSP430i2020	16	1	16	1	3	_	•	•	•	•	•	•	2 ch SD24	-40 to 105	28TSSOP, 32QFN	1.50
MSP430i2021	32	2	16	1	3	_	•	•	•	•	•	•	2 ch SD24	-40 to 105	28TSSOP, 32QFN	1.58
MSP430i2030	16	1	16	1	3	_	•	•	•	•	•	•	3 ch SD24	-40 to 105	28TSSOP, 32QFN	1.60
MSP430i2031	32	2	16	1	3	_	•	•	•	•	•	•	3 ch SD24	-40 to 105	28TSSOP, 32QFN	1.70
MSP430i2040	16	1	16	1	3	_	•	•	•	•	•	•	4 ch SD24	-40 to 105	28TSSOP, 32QFN	1.70
MSP430i2041	32	2	16	1	3	_	•	•	•	•	•	•	4 ch SD24	-40 to 105	28TSSOP, 32QFN	1.75

¹Prices are quoted in U.S. dollars and represent year 2014 suggested resale price.

*Represents number of capture/compare registers per timer.

New products are listed in **bold red**.

Device Catalog

CC430 Family

Sub-1GHz $RF + MSP430^{TM}$ MCU

The CC430 16-bit RF microcontroller family provides tight integration between the microcontroller core, peripherals,

software, and RF transceiver, creating true system-on-chip solutions that are easy to use. Features <1 GHz RF transceiver, with 1.8V-3.6V operation.

CC430	(Sub)-1G	Hz B	F+	M	SP	430 Mi	icrocontro	oller) Se	ries -	- Un	to 20	MH	7					
	Ì			16-Bi					USC									1ku	
Part Number	Flash (KB)	SRAM (KB)	I/O (max)	Total	A*	B*	Watchdog and RTC	PMM: BOR, SVS, SVM, LDO	Ch A: UART/ Lin/irda/spi		DMA	MPY	Comp B	Temp Sensor	ADC Ch/Res	Additional Features	Package(s)	Price ¹ (U.S. \$)	Common Features
F51xx																			
CC430F5123	8	2	30	2	5	3	•	•	1	1	3 ch	$32 \times 32^{\ddagger}$	_	•	6 ch	_	48QFN	2.50	
CC430F5125	16	2	30	2	5	3	•	•	1	1	3 ch	32×32 [‡]	_	•	6 ch	_	48QFN	2.60	
CC430F5133	8	2	30	2	5	3	•	•	1	1	3 ch	$32 \times 32^{\ddagger}$	•	•	6 ch ADC12	_	48QFN	4.15	
CC430F5135	16	2	30	2	5	3	•	•	1	1	3 ch	32×32 [‡]	•	•	6 ch ADC12	_	48QFN	4.30	
CC430F5137	32	4	30	2	5	3	•	•	1	1	3 ch	$32 \times 32^{\ddagger}$	•	•	6 ch ADC12	_	48QFN	5.00	450.00
CC430F5143	8	2	30	2	5	3	•	•	1	1	3 ch	32×32 [‡]	_	•	6 ch	_	48QFN	2.60	 AES HW encryption Max RF data rate
CC430F5145	16	2	30	2	5	3	•	•	1	1	3 ch	$32 \times 32^{\ddagger}$	_	•	6 ch	_	48QFN	2.70	500 kbps
CC430F5147	32	4	30	2	5	3	•	•	1	1	3 ch	$32 \times 32^{\ddagger}$	_	•	6 ch	_	48QFN	2.80	Best sensitivity: 110 dBm [†]
F61xx																			Frequency ranges:
CC430F6125	16	2	44	2	5	3	•	•	1	1	3 ch	$32 \times 32^{\ddagger}$	•	_	_	96 seg LCD	64QFN	4.35	300–348 MHz
CC430F6126	32	2	44	2	5	3	•	•	1	1	3 ch	32×32‡	•	_	_	96 seg LCD	64QFN	4.60	389–464 MHz 779–929 MHz
CC430F6127	32	4	44	2	5	3	•	•	1	1	3 ch	$32 \times 32^{\ddagger}$	•	_	_	96 seg LCD	64QFN	5.05	
CC430F6135	16	2	44	2	5	3	•	•	1	1	3 ch	$32 \times 32^{\ddagger}$	•	•	8 ch ADC12	96 seg LCD	64QFN	4.65	
CC430F6137	32	4	44	2	5	3	•	•	1	1	3 ch	32×32‡	•	•	8 ch ADC12	96 seg LCD	64QFN	5.35	
CC430F6143	8	2	44	2	5	3	•	•	1	1	3 ch	32×32‡	_	•	8 ch	_	64QFN	3.00	
CC430F6145	16	2	44	2	5	3	•	•	1	1	3 ch	32×32 [‡]	_	•	8 ch	_	64QFN	3.10	
CC430F6147	32	4	44	2	5	3	•	•	1	1	3 ch	32×32 [‡]	_	•	8 ch	_	64QFN	3.20	

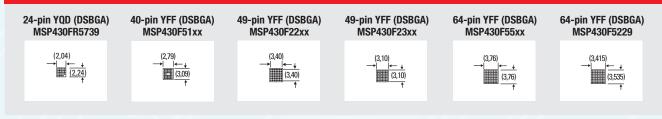
¹Prices are quoted in U.S. dollars and represent year 2014 suggested resale price.

^{*}Represents number of capture/compare register per timer.

[†]At 1.2 kBaud, 868 MHz, 1% packet error rate. †Supports 64-bit result length.

Ultra-Low-Power MSP430 MCU Selected Package Options 14-pin PW (TSSOP) 16-pin RSA (QFN) 20-pin DVG (TVSOP) 8-pin D (SOIC) 14-pin N (DIP) 20-pin PW (TSSOP) 20-pin DW (SOIC) - (19,18) -|+·(5,00)-+| → (5,00) ← → (5,00) ← → (6,50) ← įį. (10,58) (4,00) (10,30) (6,40) (6,40) 28-pin PW (TSSOP) 32-pin RTV (QFN) 20-pin N (PDIP) 24-pin RGE (QFN) 28-pin DW (SOIC) 32-pin RHB (QFN) (26,92) → (5,00) ← −(9,70)---- → (5,15) ← **4**(5,15) (5,00) Įį. (10,50) Įį, (10,30) (6,40) 40-pin RHA (QFN) 40-pin RSB (QFN) 48-pin RGZ (QFN) 48-pin DL (SSOP) 48-pin PT (LQFP) 64-pin RGC, RTD (QFN) 38-pin DA (TSSOP) —(12,50) — (9,00)→ † (6,0) (9,00) (7,00) (8,10) (10,35) (5,15) (9,00) 100-pin PZ (LQFP) 64-pin PM, PAG (LQFP/TQFP) 80-pin ZQE (BGA) 80-pin PN (LQFP) 113-pin ZQW (BGA) 128-pin PEU (LQFP) - (16,00) ----(14,00)-← (12,00) → **←**(7,00)→ **(5,00)** (5,00) (7,00) (16,20) ij (16,00) (12,00) (14,00)

Die-Size BGA Packages

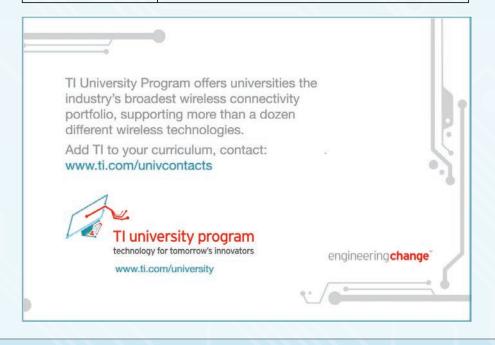


More information on package dimensions available in the datasheets or at ti.com/packaging.

Microcontroller Part Number Decoder



Processor Family	CC = Embedded RF Radio MSP = Mixed Signal Processor XMS = Experimental Silicon	
430 MCU Platform	TI's Low Power Microcontroller Platfo	orm
Device Type	Memory Type C = ROM F = FLASH FR = FRAM G = Flash (Value Line) L = No nonvolatile memory	Specialized Application AFE = Analog front end BT = Pre-programmed with Bluetooth® BQ = Contactless power CG = ROM medical FE = Flash energy meter FG = Flash medical FW = Flash electronic flow meter
Series	1 Series = Up to 8 MHz 2 Series = Up to 16 MHz 3 Series = Legacy OTP 4 Series = Up to 16 MHz w/ LCD	5 Series = Up to 25 MHz 6 Series = Up to 25 MHz w/ LCD 0 = Low-voltage series
Feature Set	Various levels of integration within a	series
Optional: A = Revision	N/A	
Optional: Temperature Range	S = 0°C to 50°C C = 0°C to 70°C I = -40°C to 85°C T = -40°C to 105°C	Y Yo-
Packaging	ti.com/packaging	
Optional: Tape and Reel	T = Small reel (7 in) R = Large reel (11 in) No markings = Tube or tray	
Optional: Additional Features	EP = Enhanced product (-40°C to 10 HT = Extreme temperature parts (-5	



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